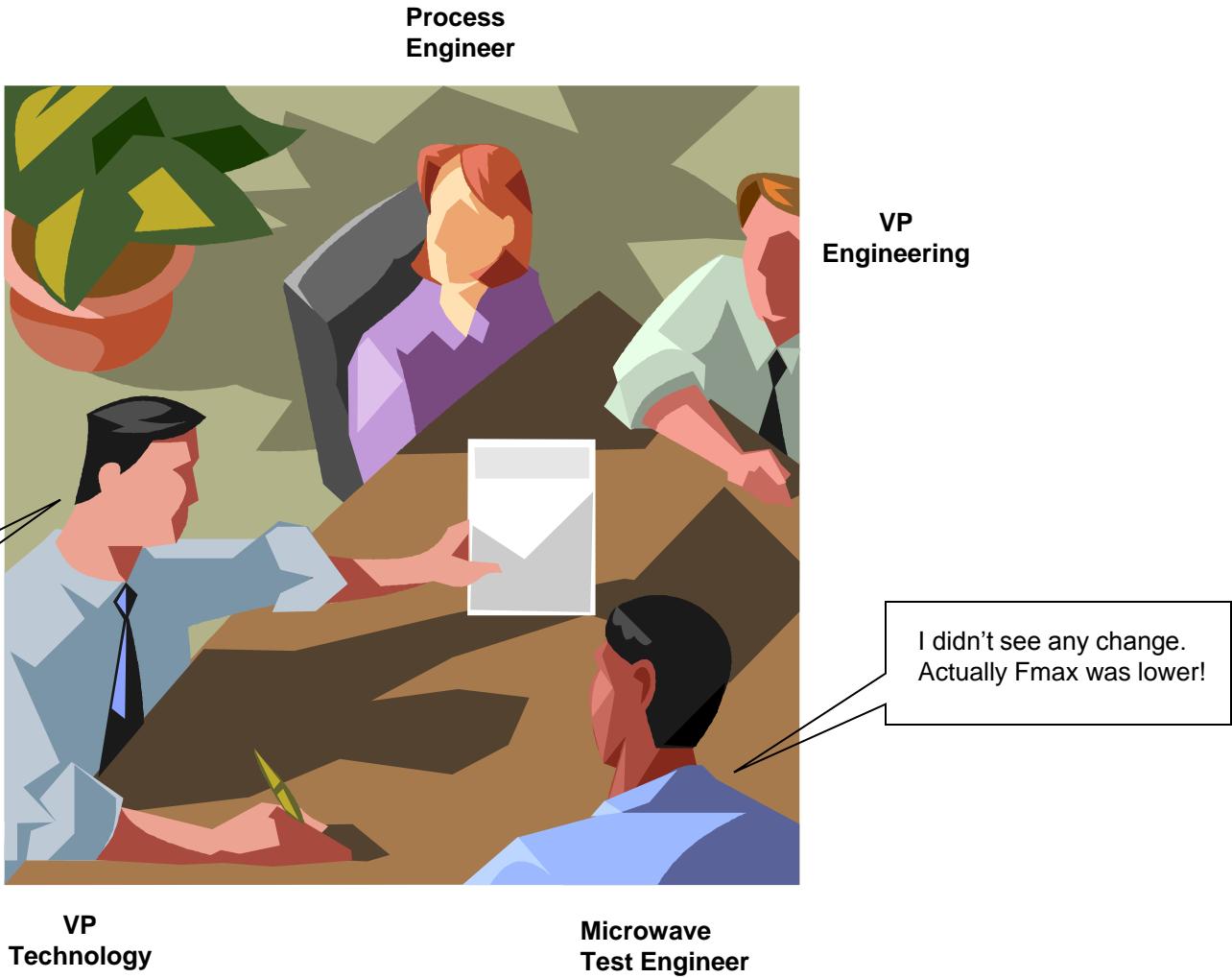
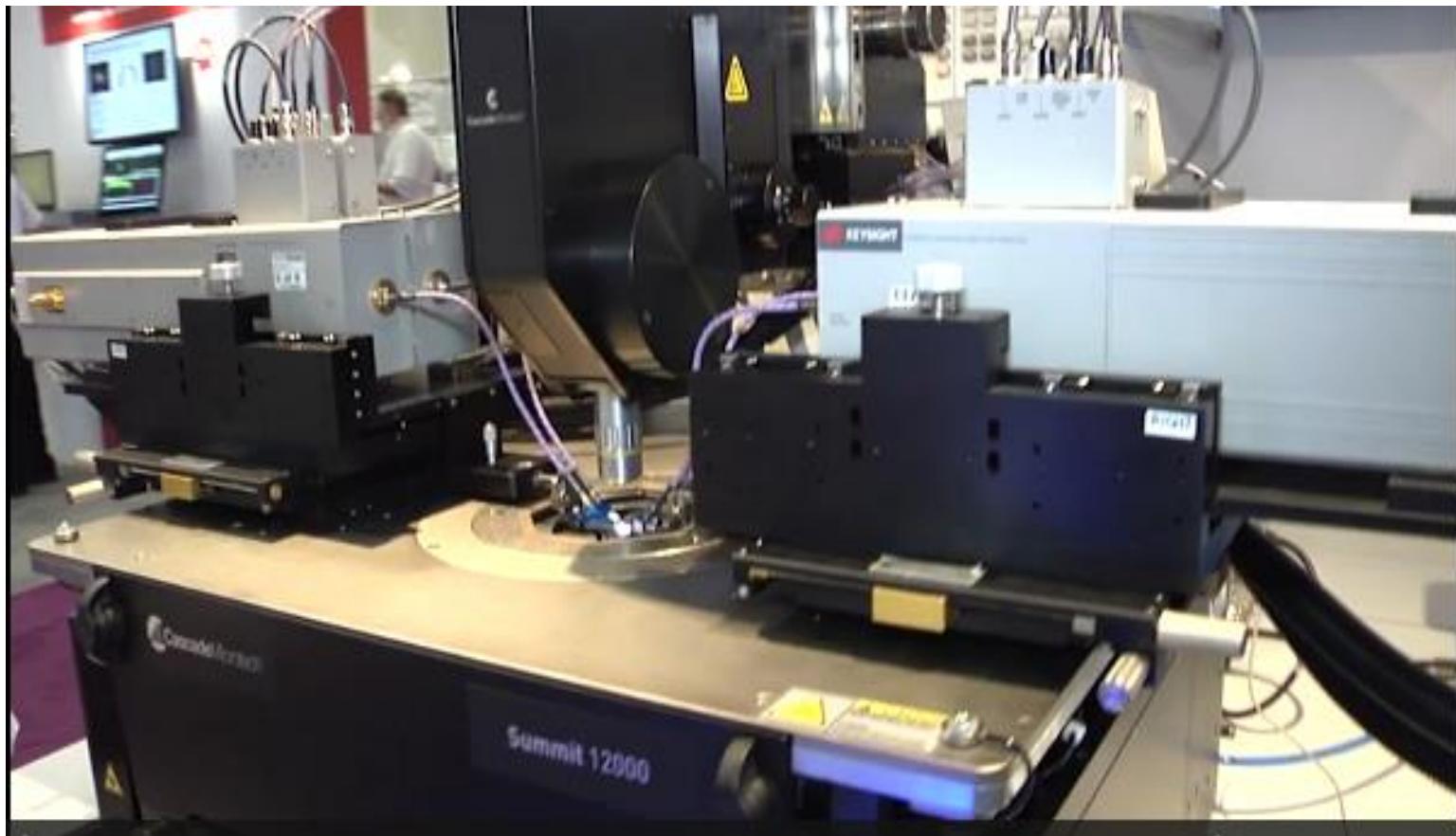


High Frequency Characterization of Transistors

J. Prasad
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1.1THz Test System from Cascade Microtech/Keysight



International Microwave Symposium, San Francisco, May 22-27, 2016

What is High Frequency Characterization?

Small Signal
Characterization

Large Signal
Characterization

This talk

→ f_T
→ f_{max}
 NF_{min}
 R_n
 $Z_s \text{ opt}$
 G_A
 R_e
 R_b
 R_s
 R_d

$P_{in} \text{ vs } P_{out}$
 PAE
 P_{1dB}
 $OIP3$
 $IIP3$
Load Pull
Source Pull

Linear Measurements

Non-Linear Measurements

OUTLINE

- Introduction
- S-parameters
- Smith Chart
- Vector Network Analyzer
- Calibration
- De-embedding
- Examples of measured data
- Gain and Stability
- F_t and F_{max} from S-parameters
- Mason's Gain
- Transistor Specmanship
- Parameter extraction/wafer maps
- Conclusion

BIPOLAR FIGURES OF MERIT

Approximate

$$f_T = \frac{g_m}{2\pi(C_\pi + C_\mu)}$$

$$C_\pi = C_{jE} + g_m \frac{W^2}{2D_n}$$

$$C_\mu = C_{jC}$$

$$f_{\max} = \sqrt{\frac{f_T}{8\pi r_{bb} C_\mu}}$$

Exact

$$\frac{1}{2\pi f_T} = \frac{N_{AB}}{N_{DE}} \left(\frac{W_E W}{2D_n} \right) + \frac{W^2}{2D_n} + \frac{W}{v_m} + \frac{W_{DC}}{2v_{sat}} + r_e C_{jE} + (r_e + r_{ee} + r_c) C_{jC}$$

τ_e

τ_b

τ_c

thermionic emission velocity

$$v_m = \sqrt{\frac{kT}{2\pi m^*}} \approx 5 \times 10^6 \text{ cm/sec for Si.}$$

saturation velocity

$$v_{sat} = 10^7 \text{ cm/sec for Si.}$$

$$f_{\max} = \sqrt{\frac{f_T}{8\pi r_{bb} C_\mu}}$$

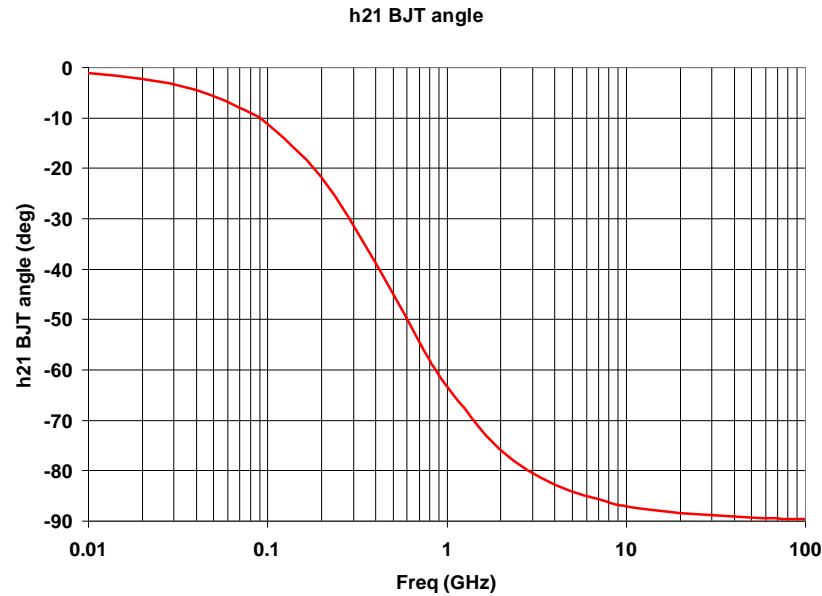
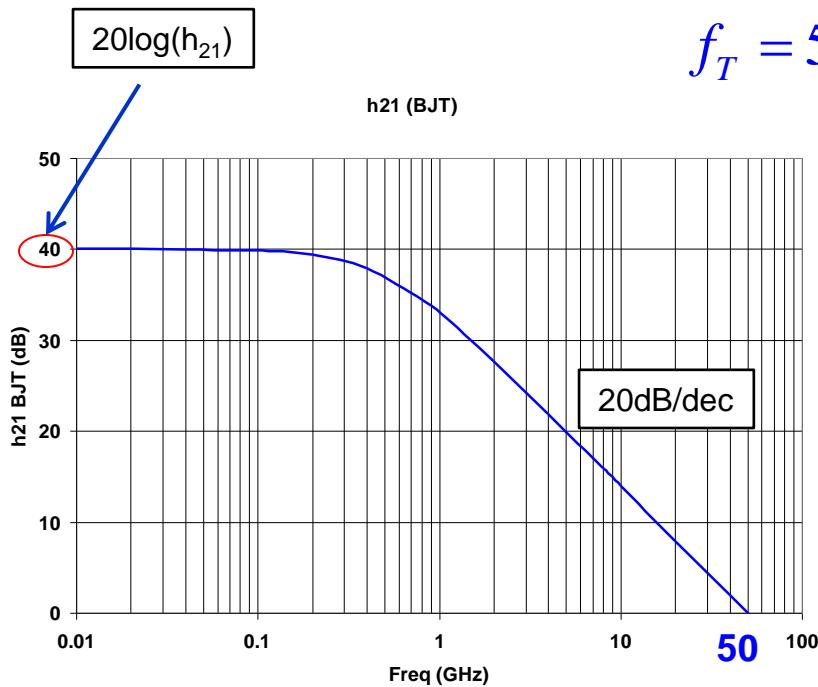
F_t VARIATION WITH FREQUENCY (Bipolar)

$$h_{21(BJT)} = \frac{\beta}{1 + j\beta \frac{f}{f_T}}$$

Microwave Engineers
find F_t by plotting
h₂₁ vs frequency!

$$\beta_{DC} = 100$$

$$f_T = 50 \text{ GHz}$$



MOS FIGURES OF MERIT

Approximate

$$f_T = \frac{g_m}{2\pi(C_{gs} + C_{gb} + C_{gd})}$$

$$f_T \approx \frac{g_m}{2\pi C_{gs}}$$

C_{gd} & C_{gb} are small in sat

$$f_{\max} = \sqrt{\frac{f_T}{8\pi R_G C_{gd}}}$$

Exact

$$f_T = \frac{g_m}{2\pi \left[(C_{gs} + C_{gd}) \left(1 + \frac{R_D + R_S}{r_o} \right) + C_{gd} g_m (R_D + R_S) + C_p \right]}$$

C_p : parasitic cap

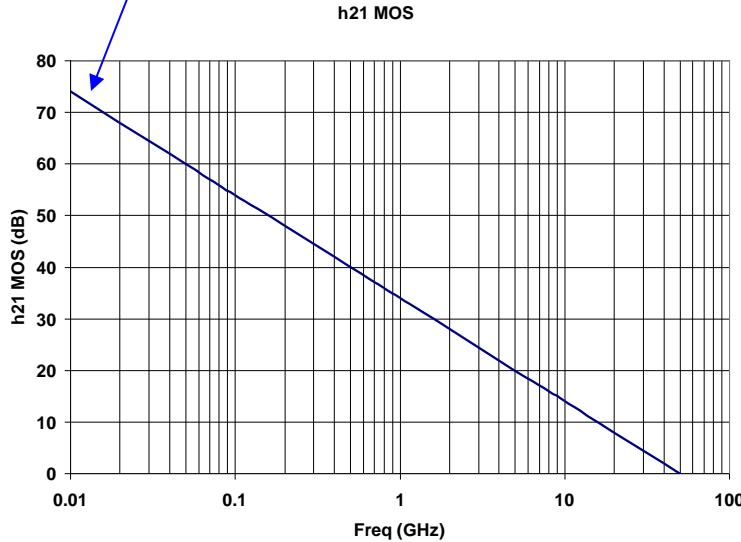
$$f_{\max} = \frac{f_T}{2\sqrt{g_{ds}(R_G + R_S) + 2\pi f_T R_G C_{gd}}}$$

F_T VARIATION WITH FREQUENCY (MOS)

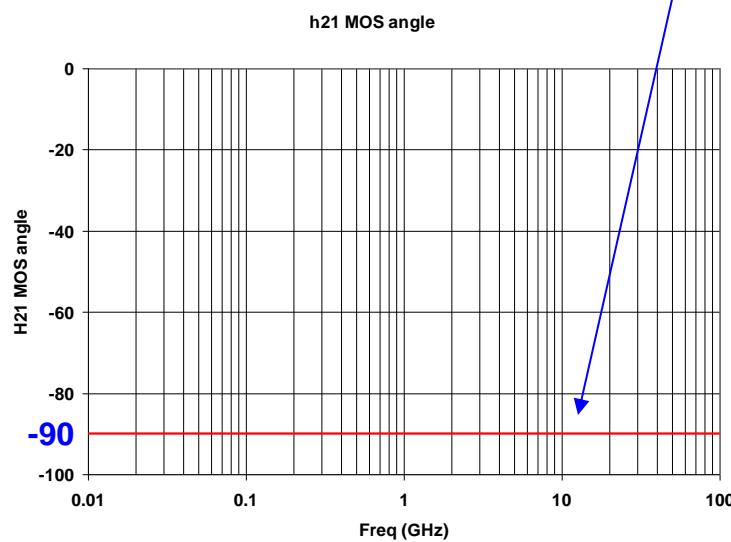
$$h_{21(MOS)} = \frac{1}{j \frac{f}{f_T}}$$

$$f_T = 50 \text{ GHz}$$

Note that this goes to infinity!



Phase is constant

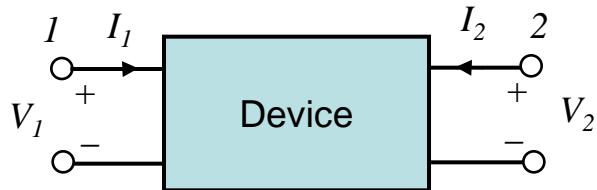


S- PARAMETERS

Why S-Parameters?

- At HF, difficult to measure currents and voltages
- Difficult to create open and shorts
- Everything behaves like Transmission lines with reflections
- S-parameters are very easy to understand and use
- S-parameters exist for any network
- Can easily relate to gain, loss, reflection and power
- Can predict the performance of cascaded networks
- From S-parameters, one can convert to Z, Y or H parameters
- Needed for SPICE model parameter extraction
- Some CAD programs need S-parameters for circuit design

Two Port Parameters



$$V_1 = h_{11}I_1 + h_{12}V_2$$

$$I_2 = h_{21}I_1 + h_{22}V_2$$

$$V_1 = z_{11}I_1 + z_{12}I_2$$

$$V_2 = z_{21}I_1 + z_{22}I_2$$

$$I_1 = g_{11}V_1 + g_{12}I_2$$

$$V_2 = g_{21}V_1 + g_{22}I_2$$

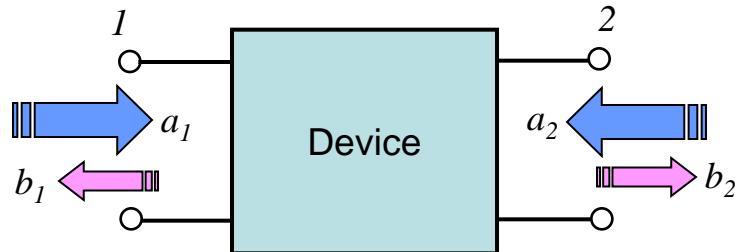
$$I_1 = y_{11}V_1 + y_{12}V_2$$

$$I_2 = y_{21}V_1 + y_{22}V_2$$

$$V_1 = AV_2 - BI_2$$

$$I_1 = CV_2 - DI_2$$

S-Parameters Defined



$$b_1 = S_{11}a_1 + S_{12}a_2$$
$$b_2 = S_{21}a_1 + S_{22}a_2$$

$$S_{11} = \frac{b_1}{a_1} \Big|_{a_2=0}$$

Input reflection coefficient with output terminated in Z_0

$$S_{21} = \frac{b_2}{a_1} \Big|_{a_2=0}$$

Forward transmission coefficient with output terminated in Z_0

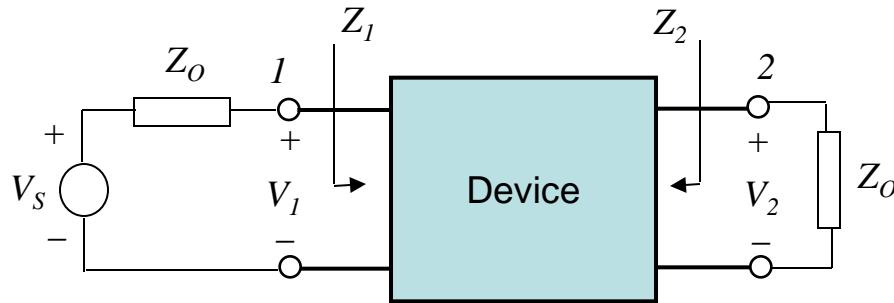
$$S_{12} = \frac{b_1}{a_2} \Big|_{a_1=0}$$

Reverse transmission coefficient with input terminated in Z_0

$$S_{22} = \frac{b_2}{a_2} \Big|_{a_1=0}$$

Output reflection coefficient with input terminated in Z_0

S-Parameters in terms of impedances and voltages



Z_o : Characteristic impedance (50Ω)

$$S_{11} = \frac{Z_1 - Z_0}{Z_1 + Z_0}$$

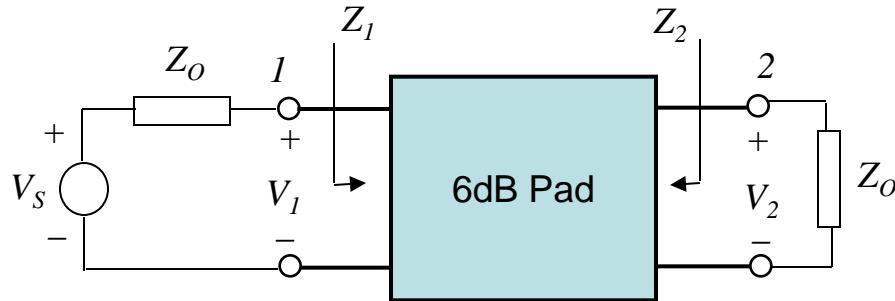
$$S_{22} = \frac{Z_2 - Z_0}{Z_2 + Z_0}$$

$$S_{21} = \frac{2V_2}{V_s}$$

$$S_{12} = \frac{2V_1}{V_s}$$

G.Gonzalez, Microwave Transistor Amplifiers,
Prentice Hall 1984

S-Parameters for a 6dB pad



$$S_{11} = \frac{Z_1 - Z_0}{Z_1 + Z_0}$$

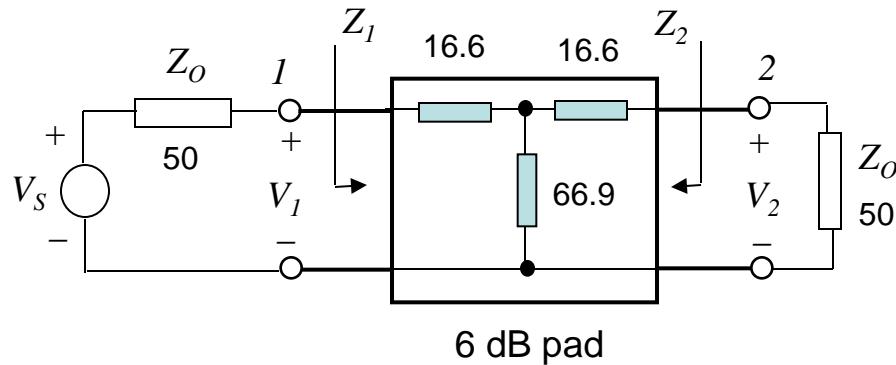
$$S_{22} = \frac{Z_2 - Z_0}{Z_2 + Z_0}$$

$$S_{21} = \frac{2V_2}{V_s}$$

$$S_{12} = \frac{2V_1}{V_s}$$

$$S = \begin{pmatrix} 0 & 0.5 \\ 0.5 & 0 \end{pmatrix}$$

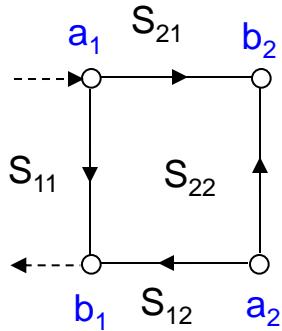
Z-Parameters for a 6dB pad



$$Z = \begin{pmatrix} 83.5 & 66.9 \\ 66.9 & 83.5 \end{pmatrix} \quad S = \begin{pmatrix} 0 & 0.5 \\ 0.5 & 0 \end{pmatrix}$$

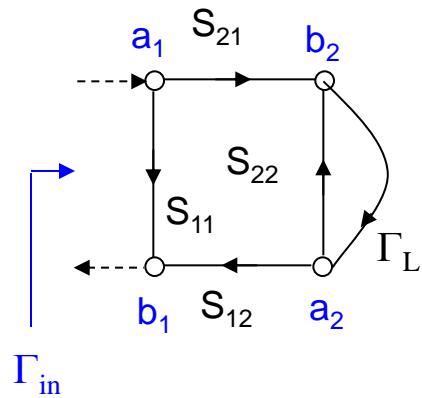
Looking at Z - parameters
one can not quickly infer
this is a 6dB Pad!

SIGNAL FLOW GRAPHS

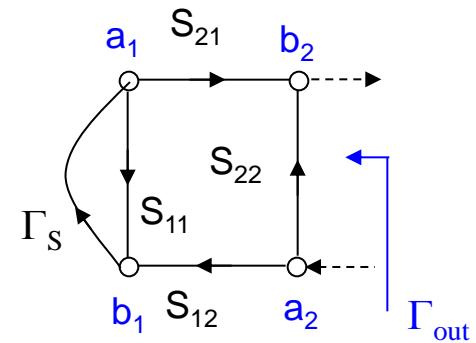


$$b_1 = S_{11}a_1 + S_{12}a_2$$

$$b_2 = S_{21}a_1 + S_{22}a_2$$



$$\Gamma_{in} = S_{11} + \frac{S_{12}S_{21}\Gamma_L}{1 - S_{22}\Gamma_L}$$



$$\Gamma_{out} = S_{22} + \frac{S_{12}S_{21}\Gamma_S}{1 - S_{11}\Gamma_S}$$

INTRODUCTION TO SMITH CHART

Mapping of resistances – Smith Chart-1

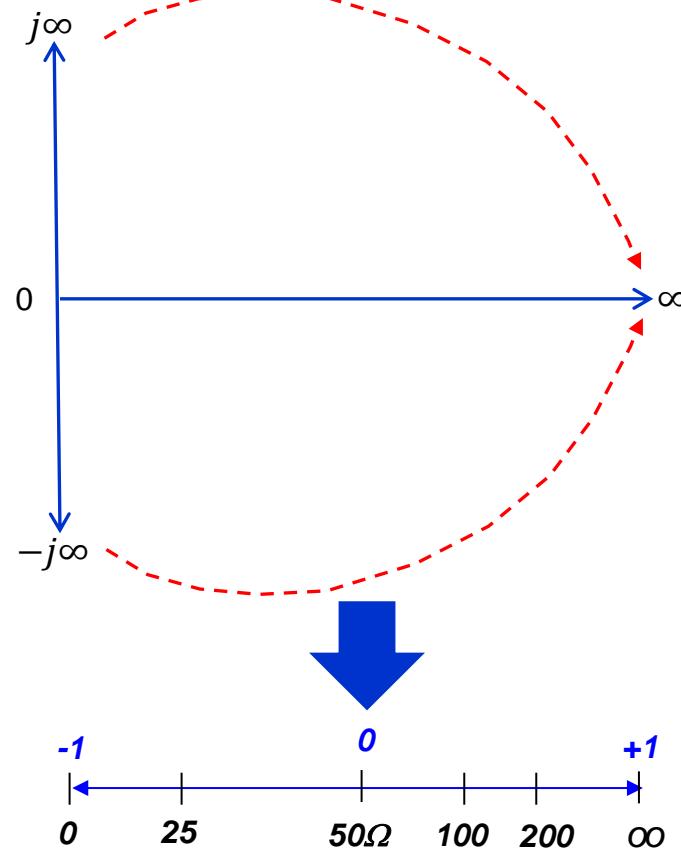
$$\Gamma_L = \frac{Z_L - Z_0}{Z_L + Z_0}$$

$$\Gamma_S = \frac{Z_S - Z_0}{Z_S + Z_0}$$

Convert all impedances to reflection coefficient and plot it. That is Smith Chart!

$$Z_0 = 50\Omega$$

Z_L ohms	Γ_L
0	-1.00
25	-0.33
50	0.00
100	0.33
200	0.60
inf	1.00



Pure resistances map along the x-axis between -1 and +1

Mapping of reactances – Smith Chart-2

$$\Gamma_L = \frac{Z_L - Z_0}{Z_L + Z_0}$$

$$Z_0 = 50\Omega$$

$$\Gamma_S = \frac{Z_S - Z_0}{Z_S + Z_0}$$

$$Z_L (\Omega)$$

$$0$$

$$j10$$

$$j25$$

$$j50$$

$$j100$$

$$j200$$

$$j\infty$$

$$\Gamma_L$$

$$1|180^\circ$$

$$1|157.4^\circ$$

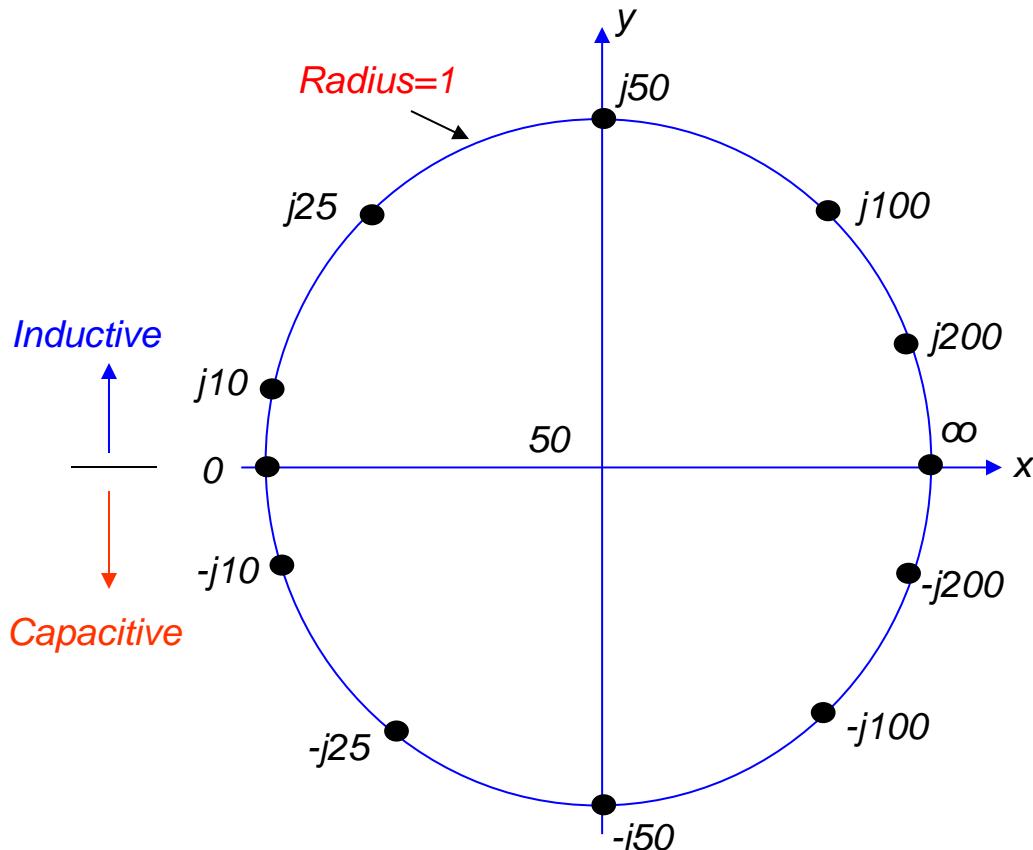
$$1|126.9^\circ$$

$$1|90^\circ$$

$$1|53.1^\circ$$

$$1|28.1^\circ$$

$$1|0^\circ$$



Note that magnitude is always 1 but angle varies.
Pure reactance maps along the circumference of a unit circle.

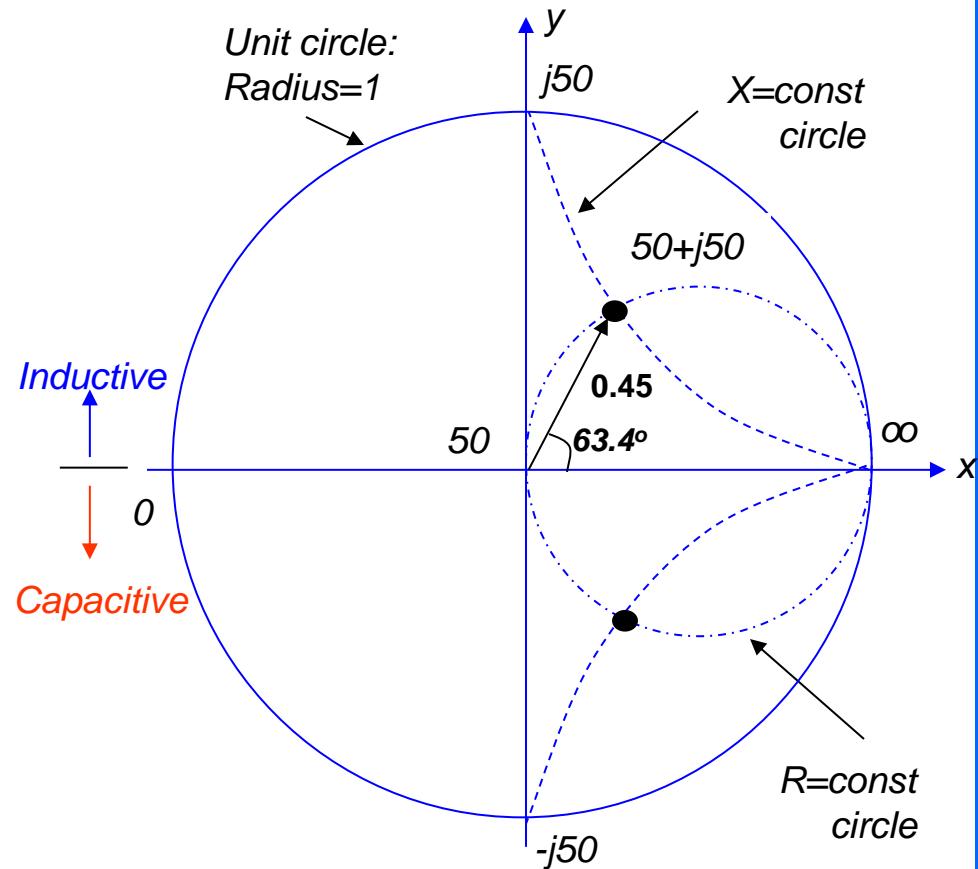
Mapping of impedances – Smith Chart-3

$$\Gamma_L = \frac{Z_L - Z_0}{Z_L + Z_0}$$

$$Z_0 = 50\Omega$$

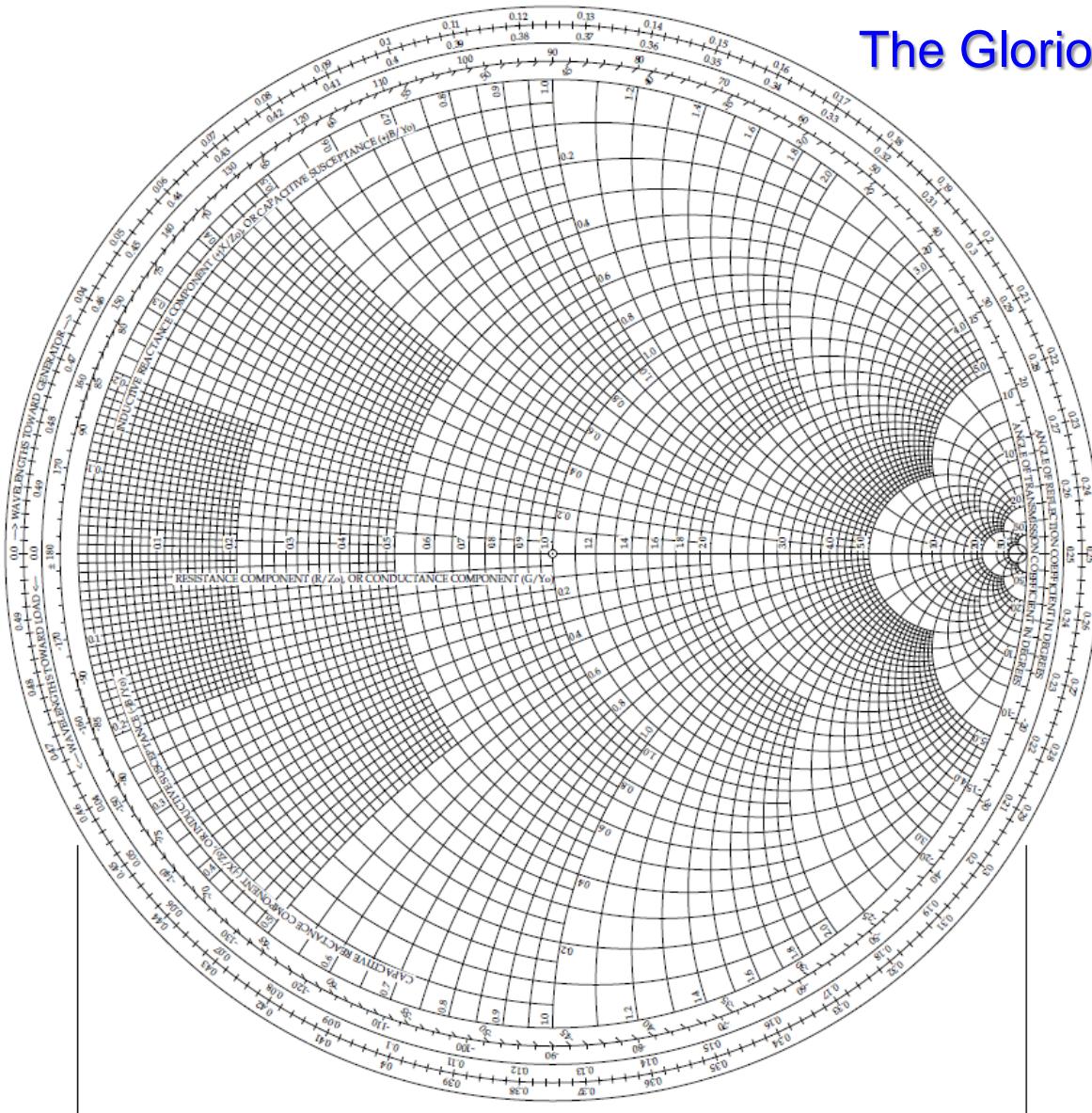
$$\Gamma_S = \frac{Z_S - Z_0}{Z_S + Z_0}$$

$Z_L(\Omega)$	Γ_L
$50+j50$	$0.45[63.4^\circ]$
$50-j50$	$0.45[-63.4^\circ]$



All impedances ($R+jX$) with $R>0$ will map inside a unit circle.
If R is negative ($R<0$), it will map outside the unit circle.

The Glorious Smith Chart



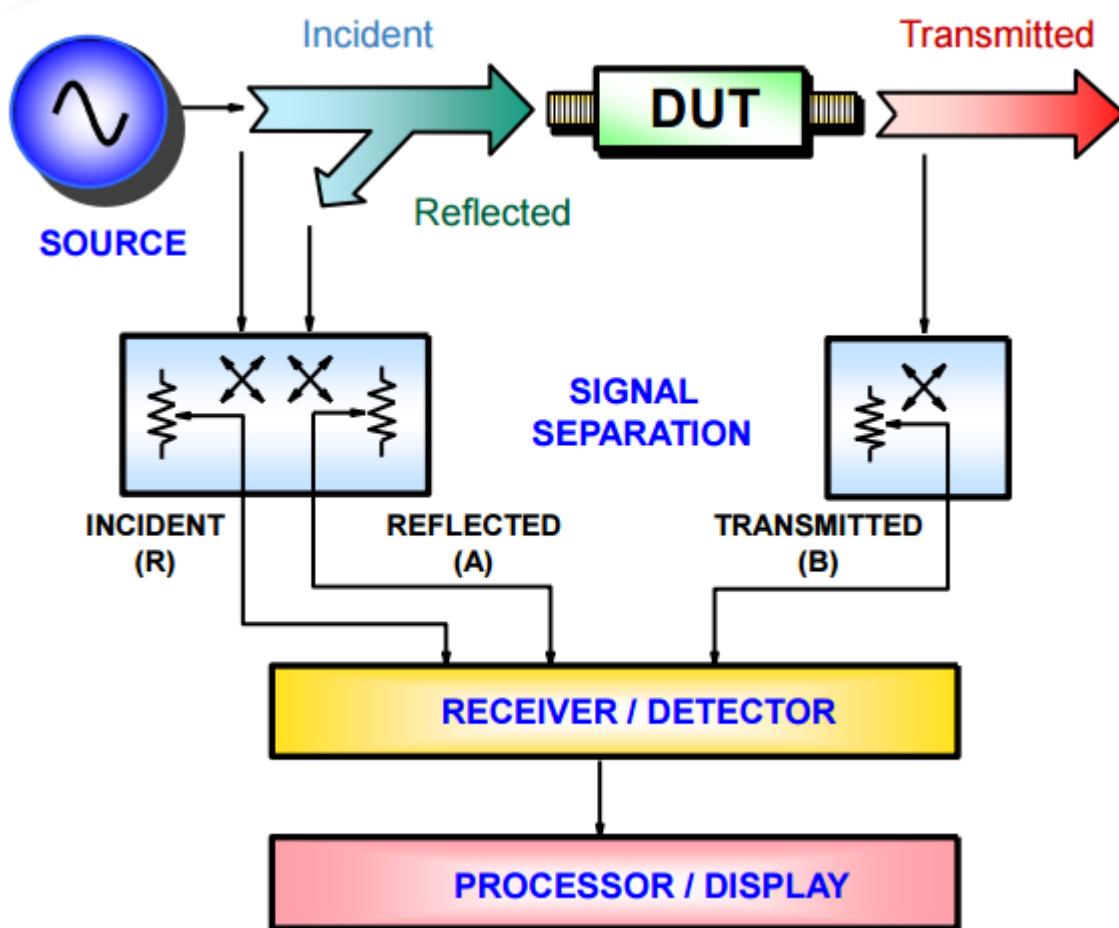
How to measure S-parameters? - The Vector Network Analyzer

E 8361C PNA Series NETWORK ANALYZER 10MHz – 67GHz



You will also need a 4155 Semiconductor Parameter Analyzer for biasing.

VECTOR NETWORK ANALYZER BLOCK DIAGRAM



What is Calibration?



CALIBRATION

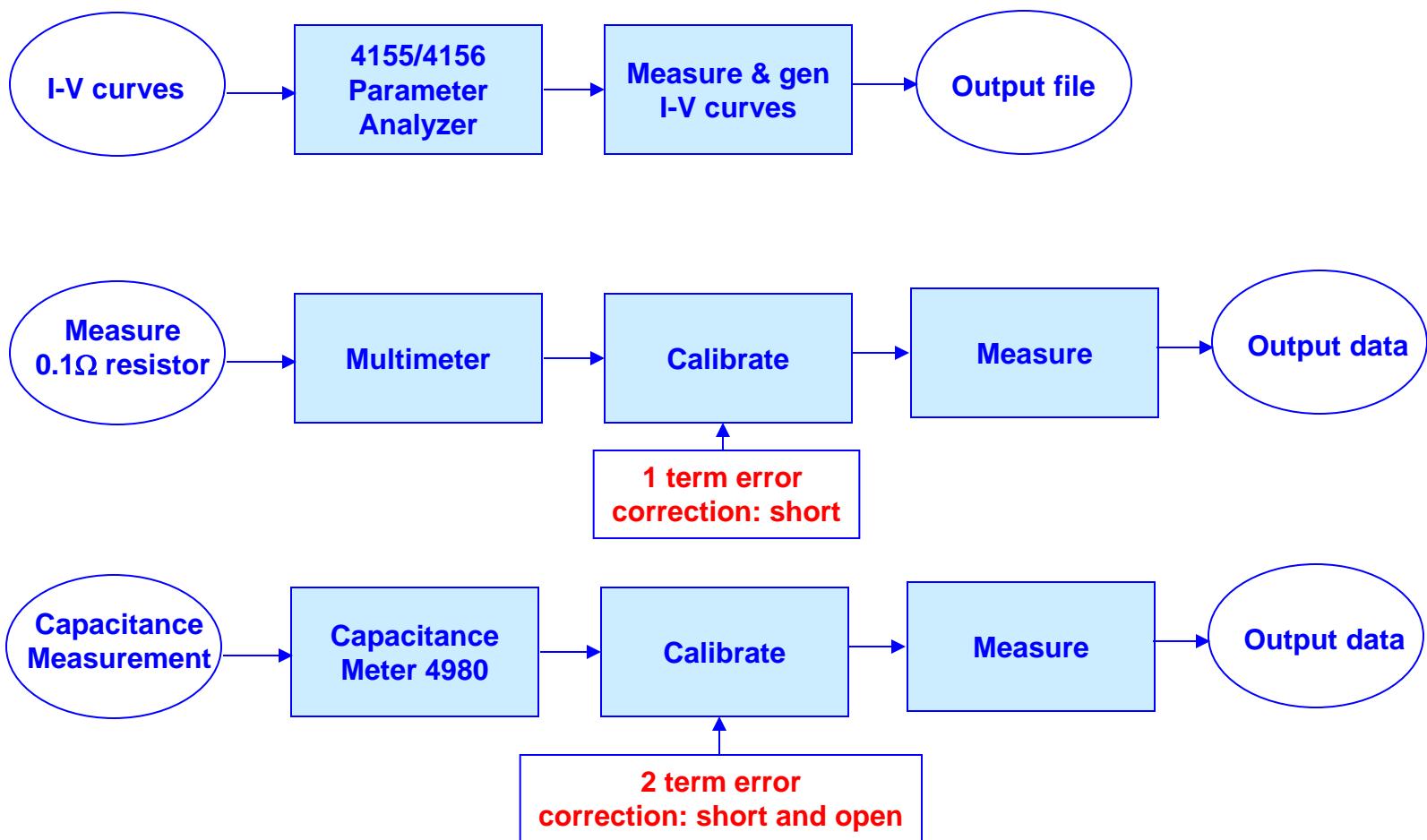
Short the leads and adjust the ZERO OHMS pot so that the meter reads zero. We have zeroed out resistance of the test leads.



CALIBRATION

Short the leads and write down the reading R1.
Connect the resistor Rx and take the reading R2.

Unknown resistor Rx = R2 – R1

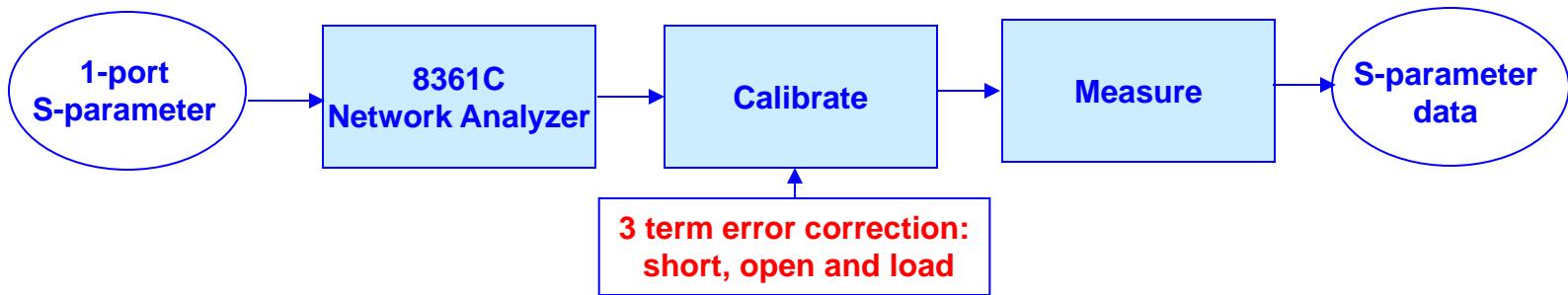


4980A CAPACITANCE METER (20Hz – 2MHz)

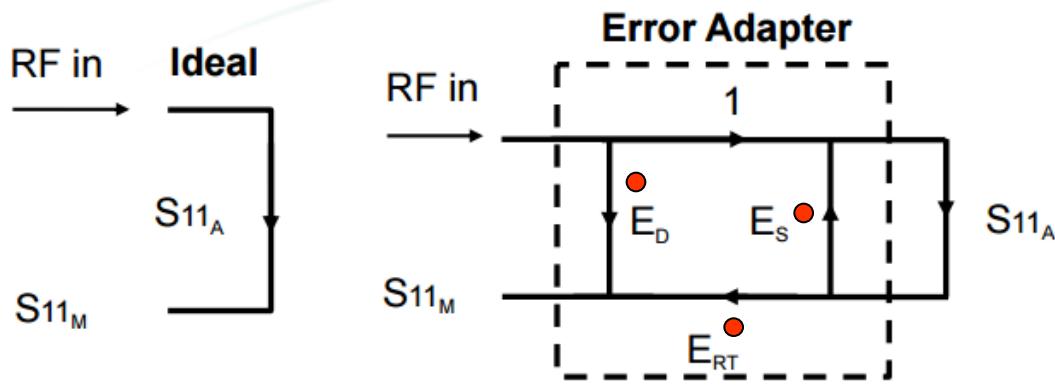


Short the leads and write down the series resistance R_s .
Open the leads and write down the stray capacitance C_p .
The instrument does the correction for the series resistance.
Then it subtracts the stray capacitance from the measured data.

One-Port Measurement using Network Analyzer



One-Port Error Correction

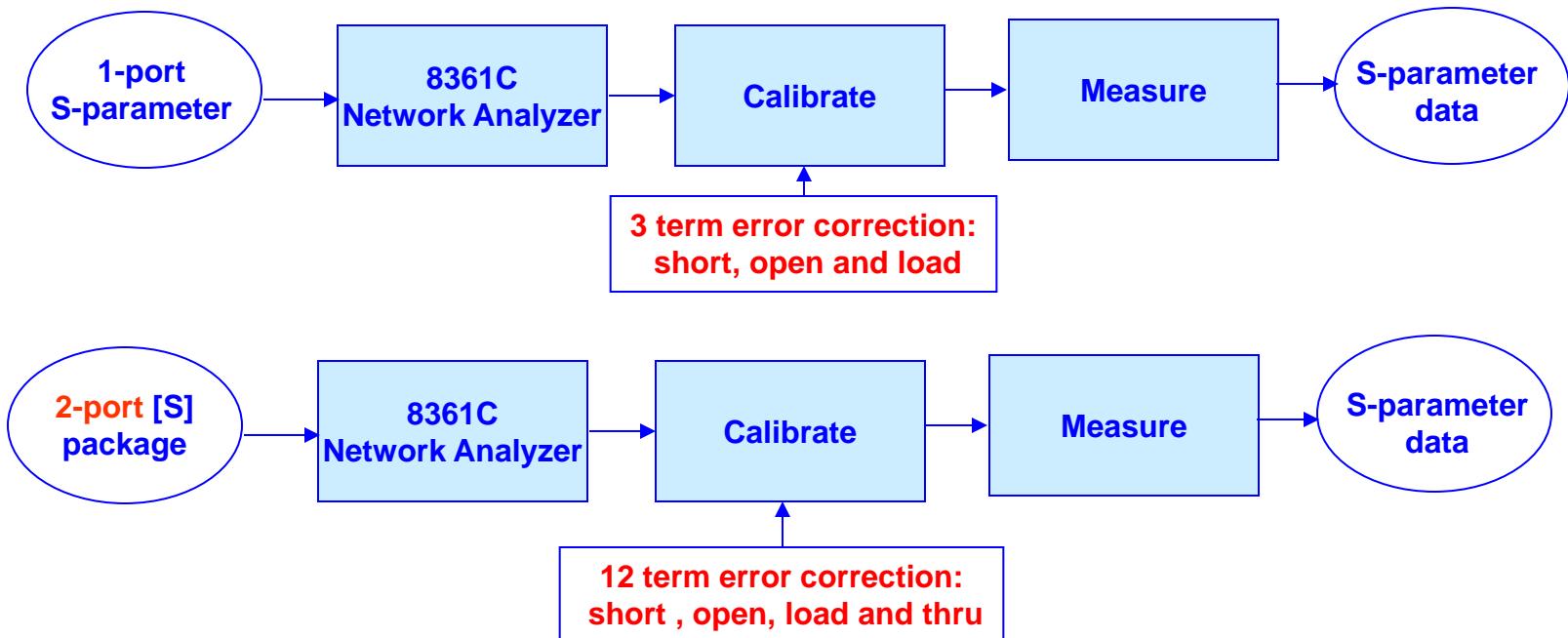


To solve for error terms, we
measure 3 standards to generate
3 equations and 3 unknowns

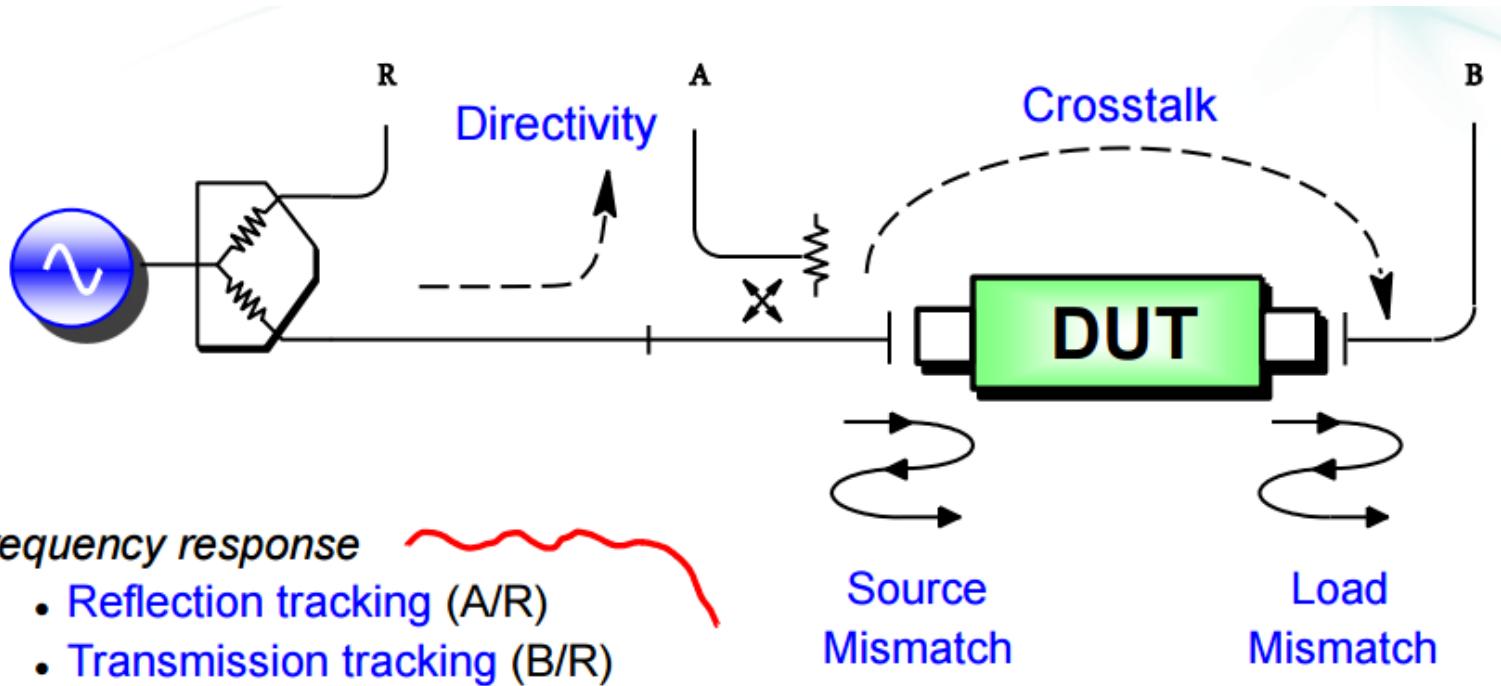
E_D = Directivity
 E_{RT} = Reflection tracking
 E_S = Source Match
 S_{11M} = Measured
 S_{11A} = Actual

$$S_{11M} = E_D + E_{RT} \left[\frac{S_{11A}}{1 - E_S S_{11A}} \right]$$

One / Two-Port Measurement using Network Analyzer



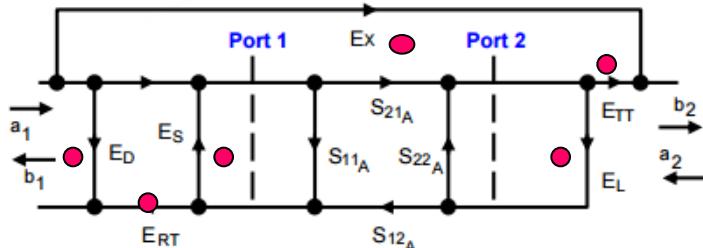
TWO PORT CALIBRATION



**Six forward and six reverse error terms
yields 12 error terms for two-port devices**

Two-Port Error Correction

Forward model



E_D = fwd directivity

E_S = fwd source match

E_{RT} = fwd reflection tracking

E_D' = rev directivity

E_S' = rev source match

E_{RT}' = rev reflection tracking

E_L = fwd load match

E_{TT} = fwd transmission tracking

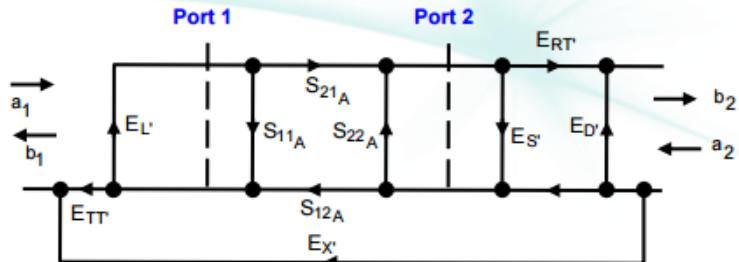
E_X = fwd isolation

$E_{L'}$ = rev load match

E_{TT}' = rev transmission tracking

E_X' = rev isolation

Reverse model



$$S_{11a} = \frac{(\frac{S_{11m} - E_D}{E_{RT}})(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} E_{S'}) - E_L (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}{(1 + \frac{S_{11m} - E_{D'}}{E_{RT}} E_S)(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} E_{S'}) - E_{L'} E_L (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}$$

$$S_{21a} = \frac{(\frac{S_{21m} - E_X}{E_{TT}})(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} (E_{S'} - E_L))}{(1 + \frac{S_{11m} - E_D}{E_{RT}} E_S)(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} E_{S'}) - E_{L'} E_L (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}$$

$$S_{12a} = \frac{(\frac{S_{12m} - E_{X'}}{E_{TT'}})(1 + \frac{S_{11m} - E_D}{E_{RT}} (E_S - E_{L'}))}{(1 + \frac{S_{11m} - E_D}{E_{RT}} E_S)(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} E_{S'}) - E_{L'} E_L (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}$$

$$S_{22a} = \frac{(\frac{S_{22m} - E_{D'}}{E_{R'}})(1 + \frac{S_{11m} - E_D}{E_{RT}} E_S) - E_{L'} (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}{(1 + \frac{S_{11m} - E_D}{E_{RT}} E_S)(1 + \frac{S_{22m} - E_{D'}}{E_{RT'}} E_{S'}) - E_{L'} E_L (\frac{S_{21m} - E_X}{E_{TT}})(\frac{S_{12m} - E_{X'}}{E_{TT'}})}$$

- Each actual S-parameter is a function of all four measured S-parameters
- Analyzer must make forward *and* reverse sweep to update any one S-parameter
- Luckily, you don't need to know these equations to **use** a network analyzers!!!

Errors and Calibration Standards

UNCORRECTED



- Convenient
- Generally not accurate
- No errors removed

RESPONSE

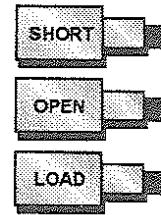


- Easy to perform
- Use when highest accuracy is not required
- Removes frequency response error

Other errors:

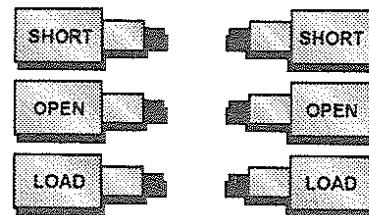
Random Errors: Noise, Repeatability Drift

1-PORT



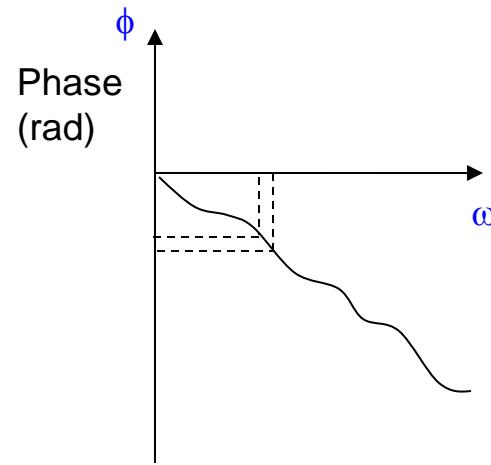
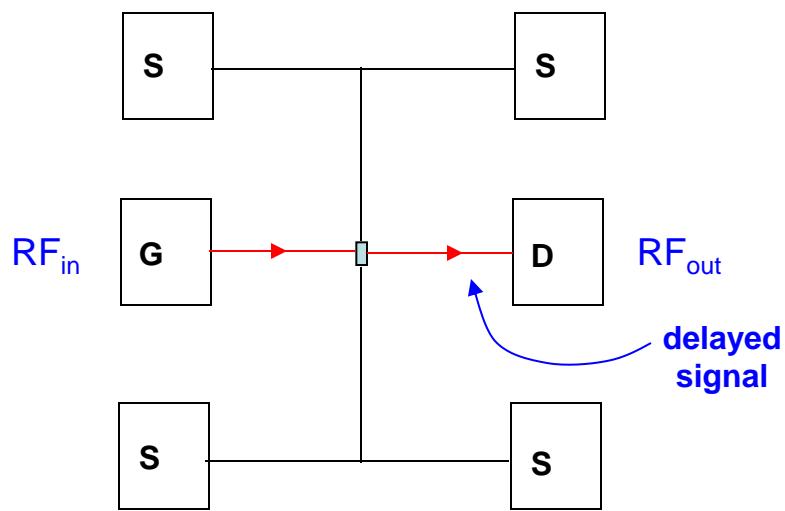
- For reflection measurements
- Need good termination for high accuracy with two-port devices
- Removes these errors:
 Directivity
 Source, load match
 Source match
 Reflection tracking

FULL 2-PORT



- Highest accuracy
- Removes these errors:
 Directivity
 Source, load match
 Reflection tracking
 Transmission tracking
 Crosstalk

THRU CALIBRATION FOR GROUP DELAY



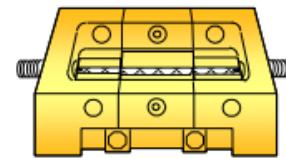
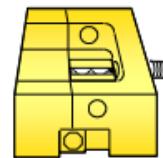
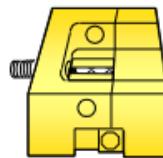
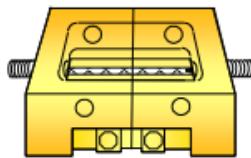
$$\begin{aligned} \text{Group delay } t_g &= -\frac{\partial \phi}{\partial \omega} \\ &= -\frac{1}{360^\circ} \frac{\partial \theta}{\partial f} \end{aligned}$$

Thru-Reflect-Line (TRL) Calibration

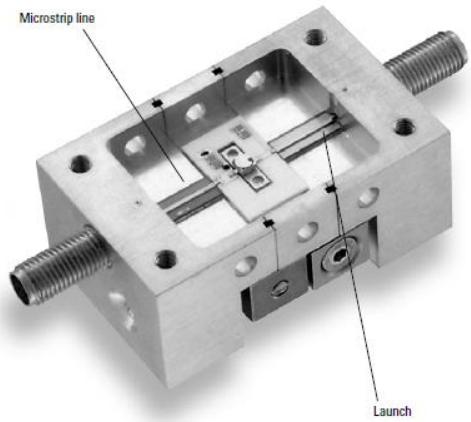
We know about Short-Open-Load-Thru (SOLT) calibration... What is TRL?

- A two-port calibration technique
- Good for non-coaxial environments (waveguide, fixtures, wafer probing)
- Characterizes same 12 systematic errors as the more common SOLT cal
- Uses practical calibration standards that are easily fabricated and characterized
- Other variations: Line-Reflect-Match (LRM), Thru-Reflect-Match (TRM), plus many others

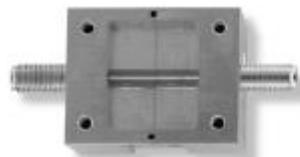
TRL was developed for
non-coaxial microwave
measurements



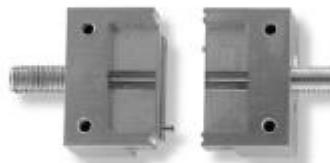
TRL CALIBRATION



At low frequencies, the lines become long.
So, we need different TRL structures for
different frequency bands for wide band
characterization. Use SOLT for lower freq.



$$\begin{bmatrix} 0 & 1 \\ 1 & 0 \end{bmatrix}$$



$$\begin{bmatrix} \Gamma & 0 \\ 0 & \Gamma \end{bmatrix}$$

REFLECT



$$\begin{bmatrix} 0 & e^{-\gamma l} \\ e^{-\gamma l} & 0 \end{bmatrix}$$

LINE

Glenn Engen, Cletus Hoer, MTT-27 (12), Dec 1979

RF MICROWAVE PROBES (CASCADE MICROTECH)

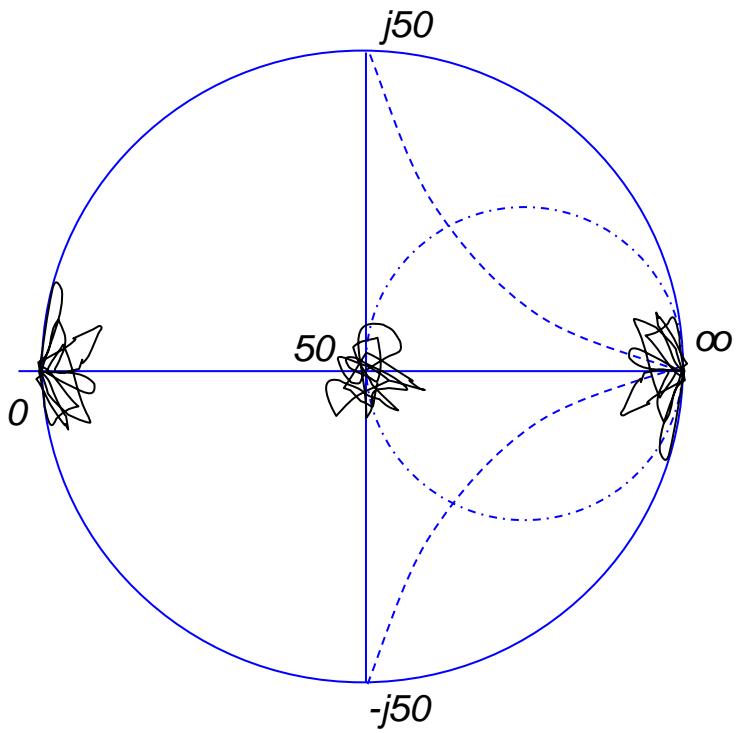


CALIBRATION USING IMPEDANCE STANDARD SUBSTRATES

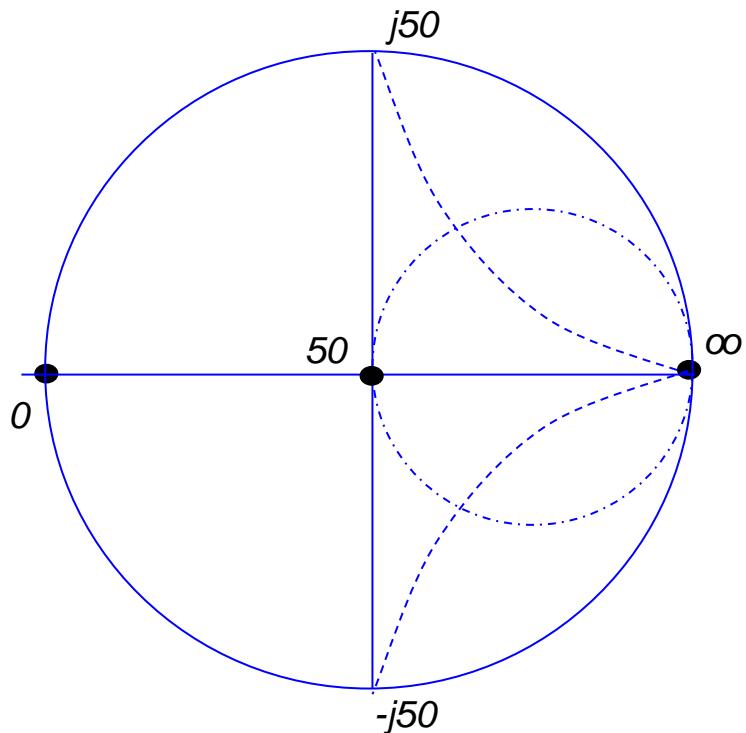


The purpose of Cal
is to bring the reference
plane to the probe tips

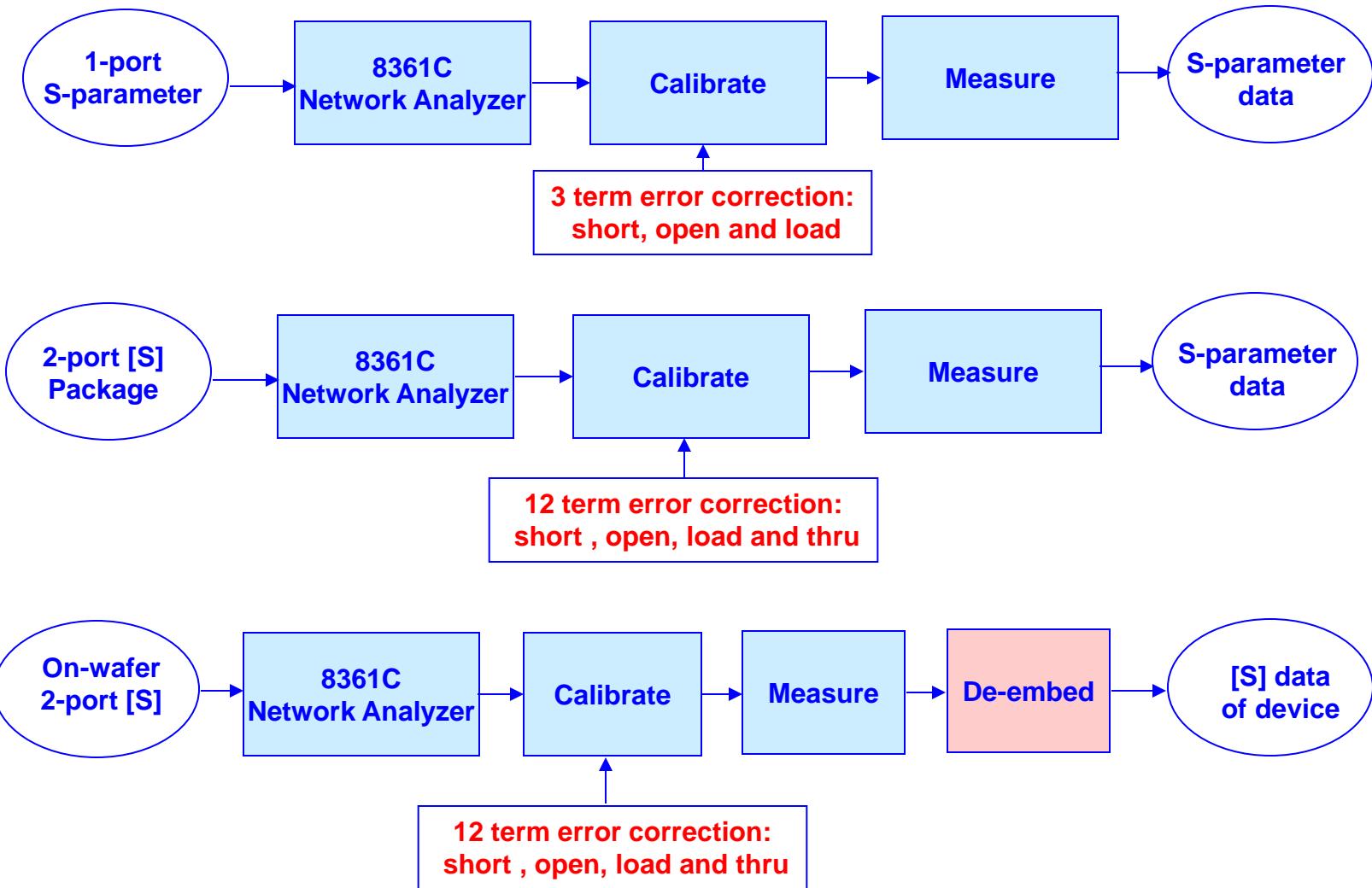
BEFORE CALIBRATION

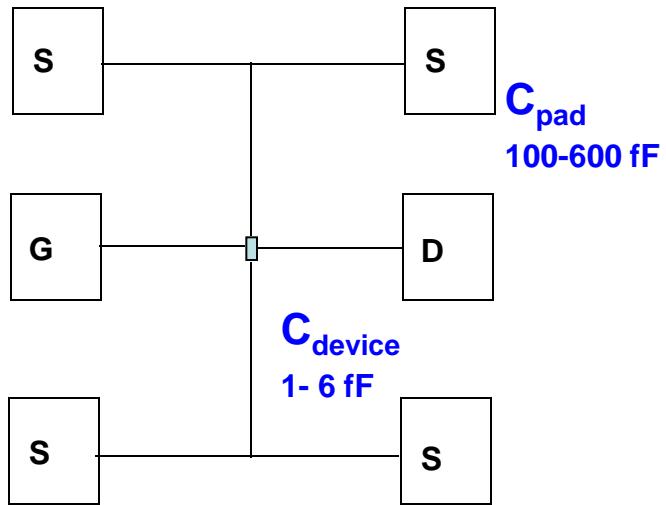


AFTER CALIBRATION

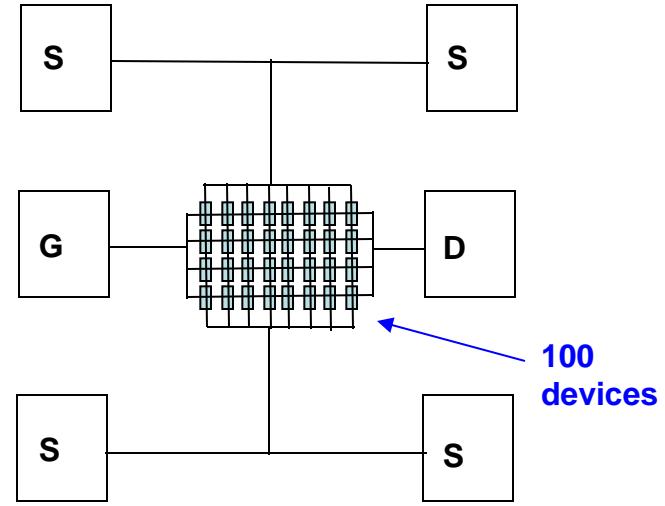


DE- EMBEDDING

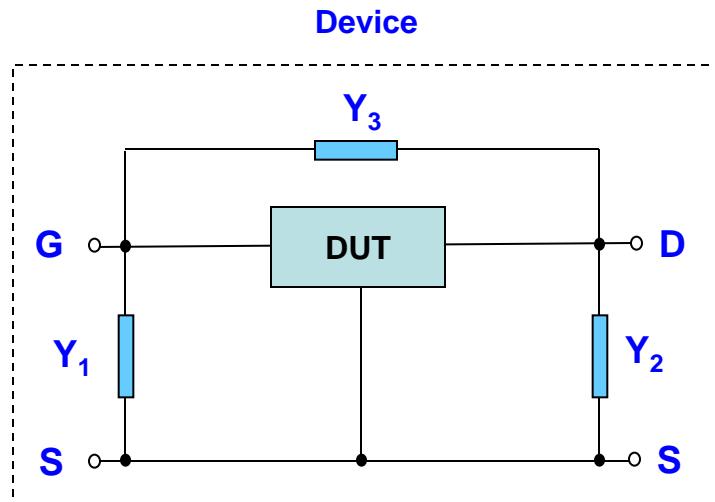




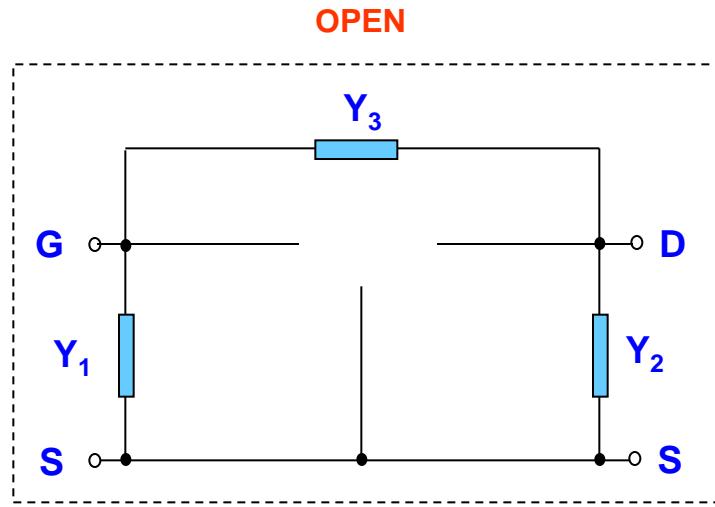
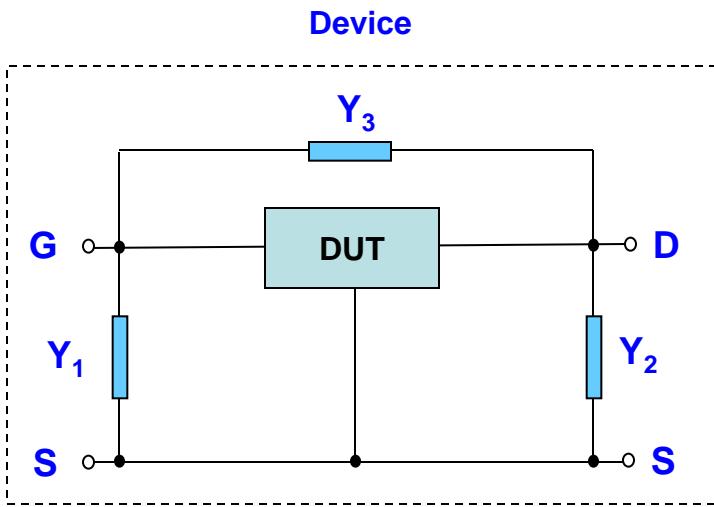
Pad capacitance far exceeds
Single device capacitance



A device array alleviates
this problem to some extent



1-Step De-Embedding



$$[S]_{open} \rightarrow [y]_{open}$$

$$[S]_{device} \rightarrow [y]_{device}$$

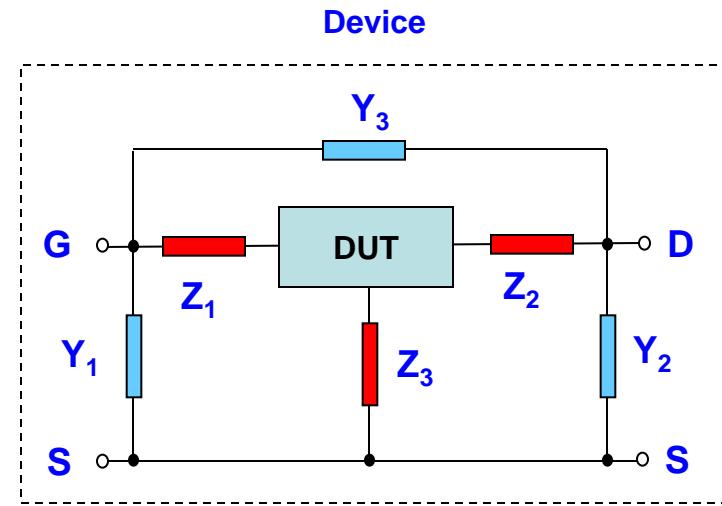
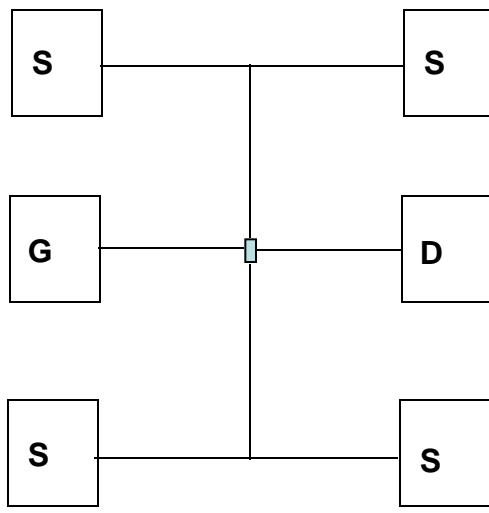
$$[y]_{DUT} = [y]_{device} - [y]_{open}$$

$$[y]_{DUT} \rightarrow [S]_{DUT}$$

Measure on-wafer OPEN
Measure DEVICE
Use the equations on the left

DE-EMBEDS PAD CAPACITANCE ONLY !

2- Step De - Embedding

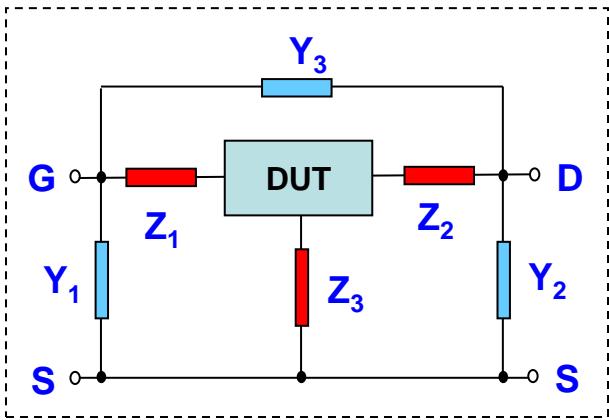


DE- EMBEDS

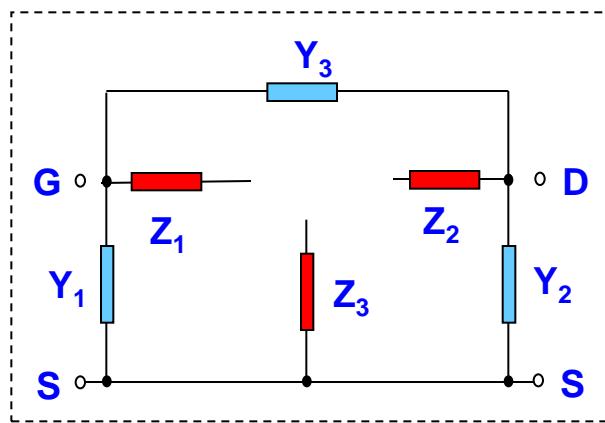
- Pad Capacitance
- Series Impedance

2- Step De - Embedding

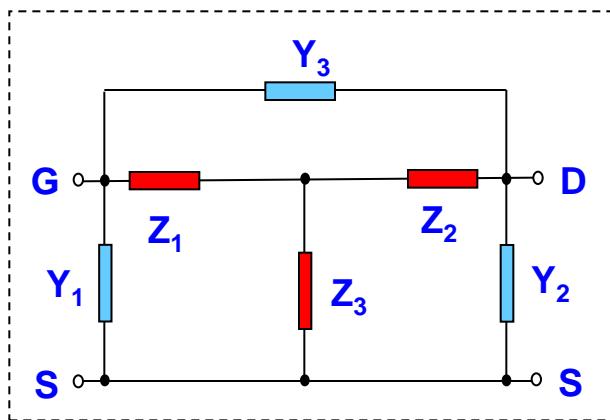
Device



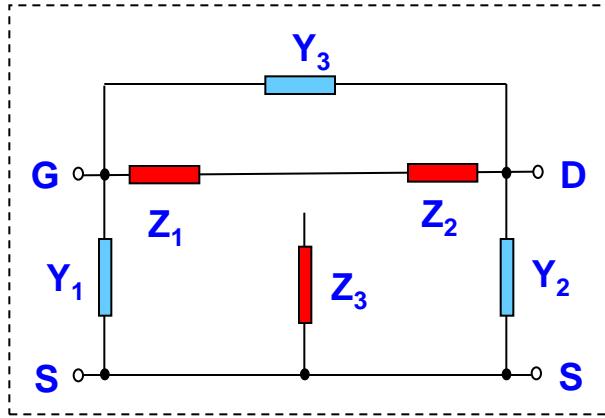
OPEN



SHORT



THRU



2- Step De - Embedding

$$[S]_{open} \rightarrow [y]_{open}$$

$$[S]_{short} \rightarrow [z]_{short}$$

$$[S]_{device} \rightarrow [y]_{device}$$

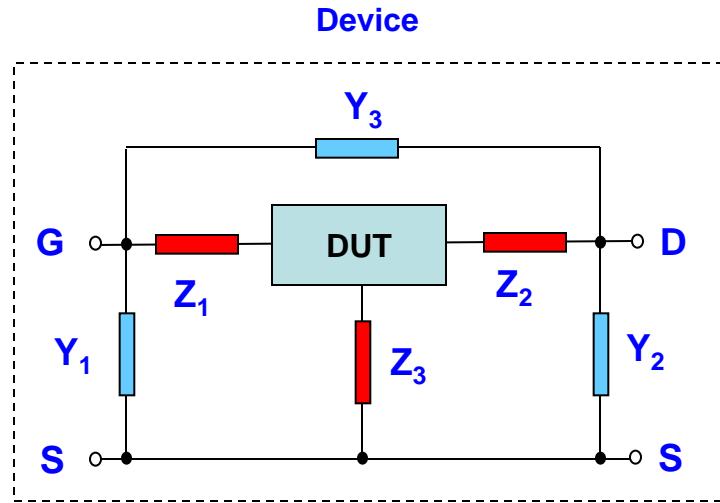
$$[y]_{dev_no_pad} = [y]_{device} - [y]_{open}$$

$$[y]_{dev_no_pad} \rightarrow [z]_{dev_no_pad}$$

$$[z]_{DUT} = [z]_{dev_no_pad} - [z]_{short}$$

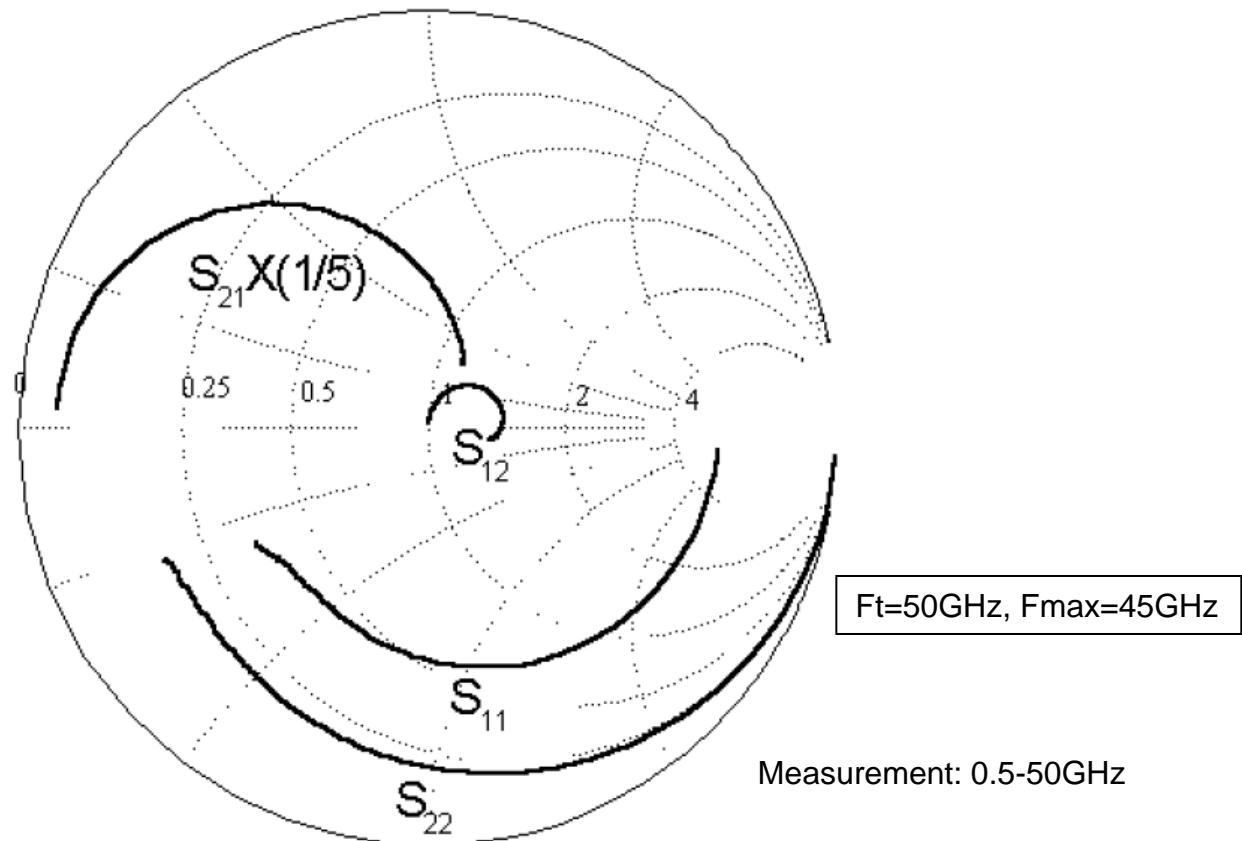
$$[z]_{DUT} \rightarrow [S]_{DUT}$$

Whoa!



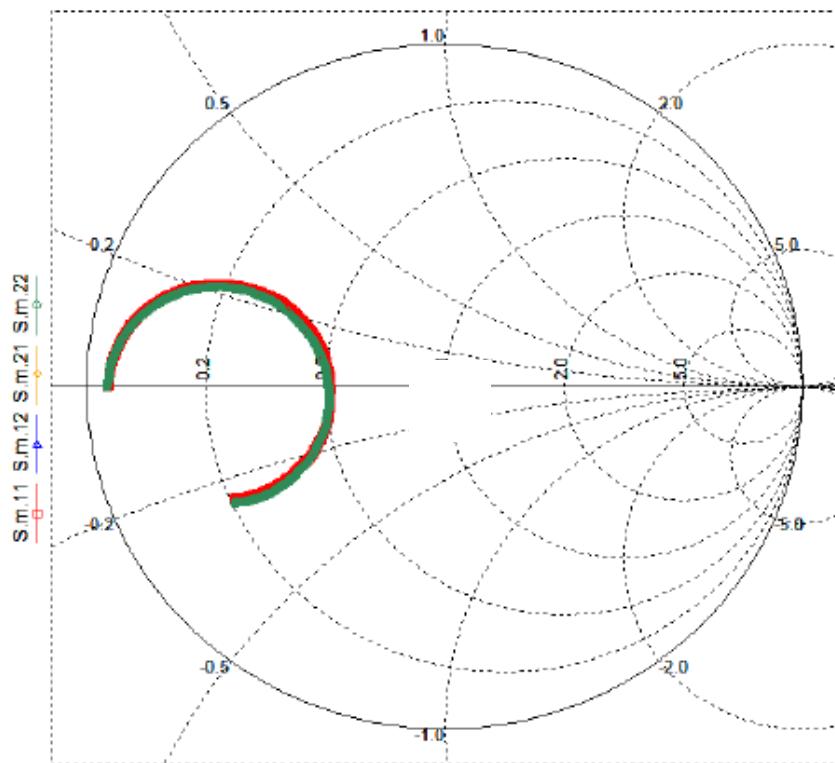
DUT with Pad capacitance
and series elements

High Frequency Performance of 0.18um CMOS

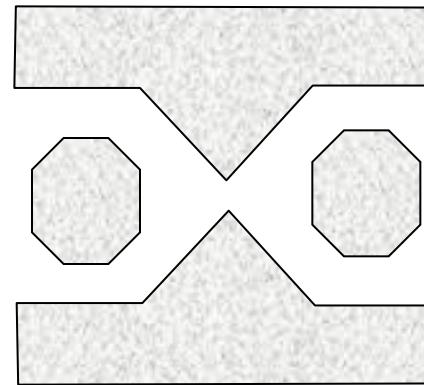
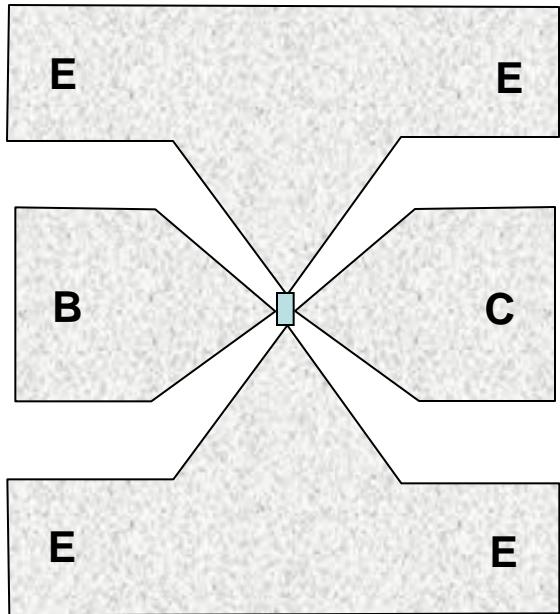


RF Characteristics of 0.18-m CMOS Transistors: Kwangseok Han, Jeong-hu Han, Minkyu Je and Hyungcheol Shin Department of Electrical Engineering and Computer Science, Korea Advanced Institute of Science and Technology, Taejon 305-701

IMPERFECT on-wafer SHORT



Layout with minimum inductance and reflections



Small octagonal pads
to reduce capacitance
and reflections

Definitions of Gain and Stability

DEFINITIONS OF GAIN

Any three terminal device will have A.C current gain. We can then define a transition frequency f_T at which the short circuit current gain becomes unity. This is one figure of merit.

$$h_{21} = \left. \frac{I_2}{I_1} \right|_{V_2=0} \quad h_{21} = 1 \quad \text{at} \quad f = f_T$$

Any three terminal active device will have power gain $G_p = \frac{P_L}{P_{IN}}$

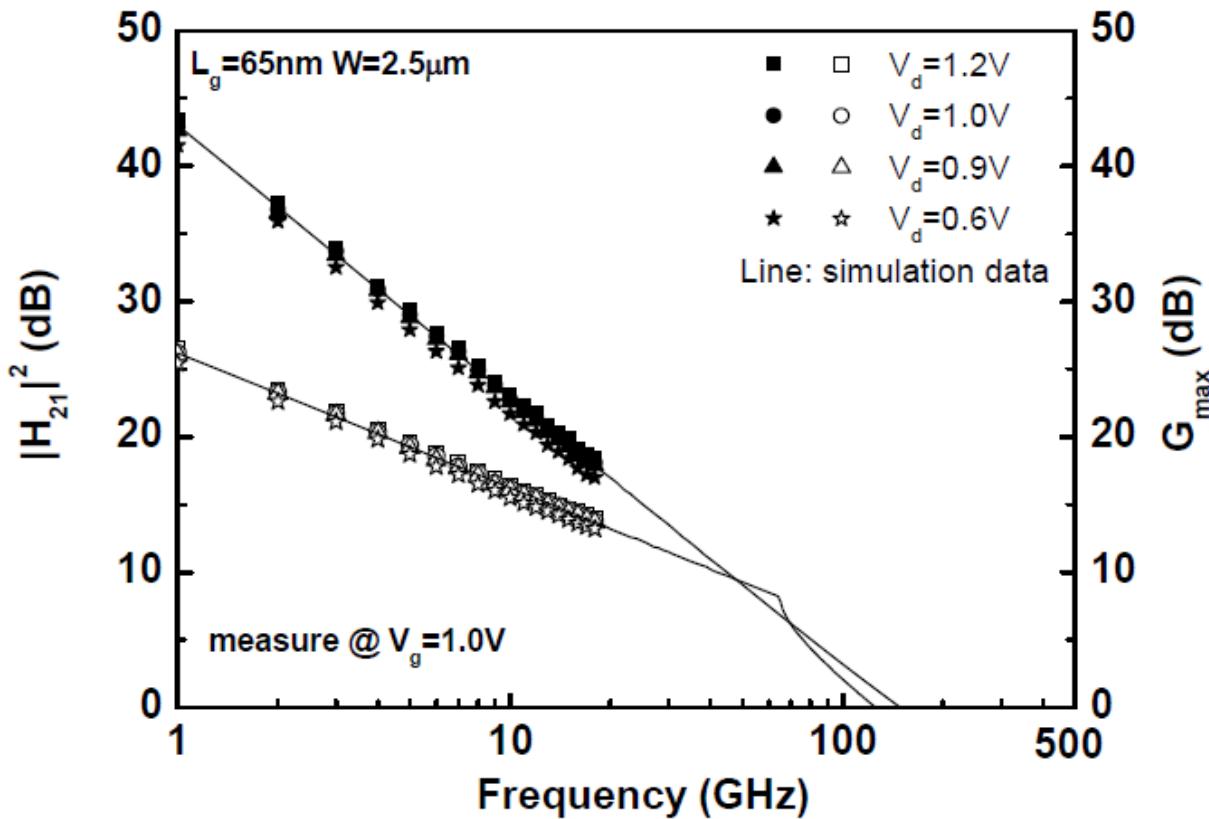
Since P_L depends on load impedance and P_{IN} depends on source impedance it is meaningful to define Available Power Gain as:

$$G_A = \frac{P_{AVN}}{P_{AVS}} = \frac{\text{Power available from the network}}{\text{Power available from the source}}$$

The frequency at which the Maximum Available Gain (MAG) becomes unity is defined as f_{max} . This is another figure of merit.

$$MAG = 1 \quad \text{at} \quad f = f_{max}$$

F_t and Fmax of 65nm CMOS



Limiting Factors of RF Performance Improvement as Down-scaling to 65-nm Node MOSFETs

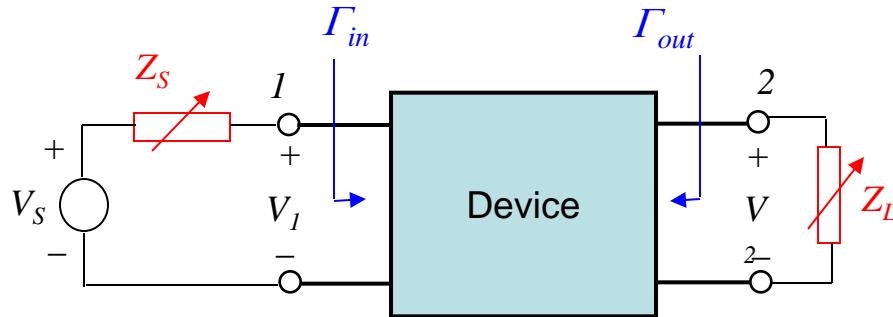
H. L. Kao^a, B. S. Lina, C. C. Liaob, M. H. Chenc, C. H. Wuc, and Albert Chinb

a Dept. of Electronic Engineering, Chang Gung Univ., Tao-Yuan, Taiwan, ROC

b Nano-Sci. Tech. Ctr, EE. Dept., Nat'l Chiao-Tung Univ., UST, Hsinchu, Taiwan, ROC

c Dept. of MicroElectronics Engineering, Chung Hua Univ., Hsinchu, Taiwan, ROC

CIRCUIT FOR MEASURING MAXIMUM AVAILABLE GAIN & Fmax



We vary Z_s and Z_L so as to provide a simultaneous conjugate match.

This maximizes the input power and delivers maximum output power to the load.
This will give us MAG.

If we do this at each frequency, we can generate a plot of MAG vs frequency.
From this plot, we can determine the frequency at which the power gain will become unity. This is Fmax.

THE EFFECT OF LOAD IMPEDANCE

$$S_{11} = 0.65 \angle -95^\circ$$

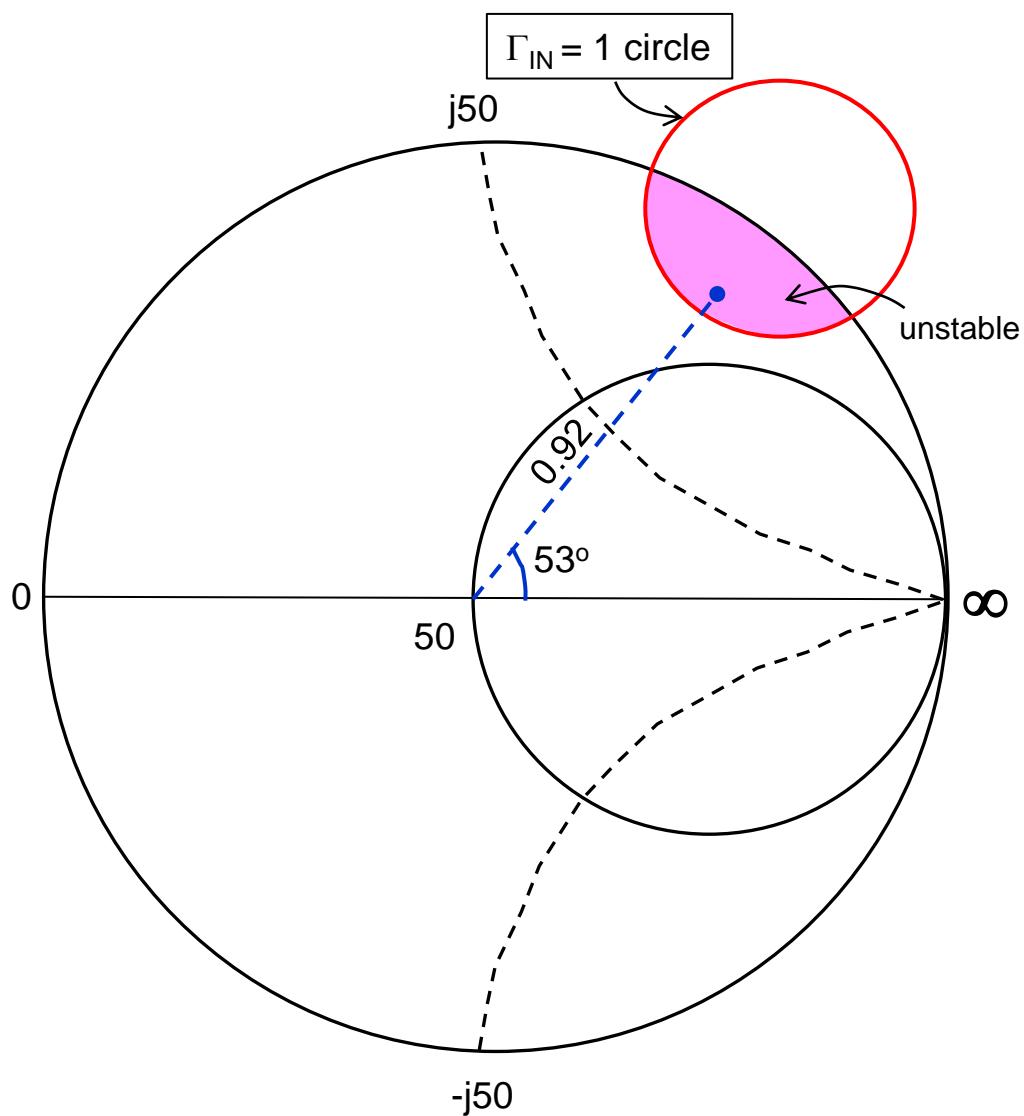
$$S_{12} = 0.04 \angle 40^\circ$$

$$S_{21} = 5.00 \angle 115^\circ$$

$$S_{22} = 0.80 \angle -35^\circ$$

$$\Gamma_{in} = S_{11} + \frac{S_{12}S_{21}\Gamma_L}{1-S_{22}\Gamma_L}$$

Z_L (ohms)	Γ_L	Γ_{in}	Stable ?
$50+j0$	0	$0.65 \angle -95^\circ$	Yes
$35+j100$	$0.77 \angle 49^\circ$	$0.91 \angle -108^\circ$	Yes
$10+j100$	$0.92 \angle 53^\circ$	$1.07 \angle -103^\circ$	Unstable



THE EFFECT OF SOURCE IMPEDANCE

$$S_{11} = 0.65 \angle -95^\circ$$

$$S_{12} = 0.04 \angle 40^\circ$$

$$S_{21} = 5.00 \angle 115^\circ$$

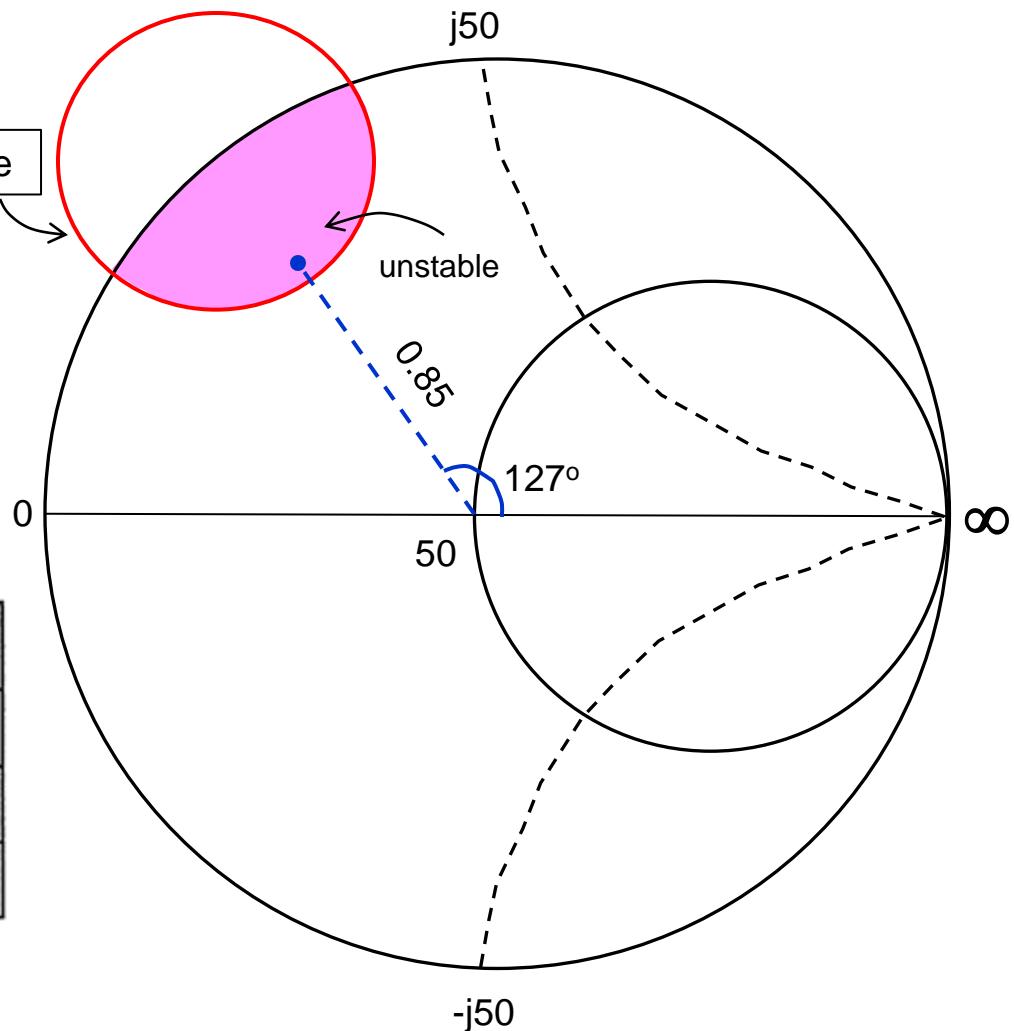
$$S_{22} = 0.80 \angle -35^\circ$$

$$\Gamma_{out} = S_{22} + \frac{S_{12}S_{21}\Gamma_s}{1-S_{11}\Gamma_s}$$

Z_s (ohms)	Γ_s	Γ_{out}	Stable ?
$50+j0$	0	$0.80 \angle -35^\circ$	Yes
$10+j25$	$0.73 \angle 125^\circ$	$0.99 \angle -39^\circ$	Yes
$5+j25$	$0.85 \angle 127^\circ$	$1.04 \angle -38^\circ$	Unstable

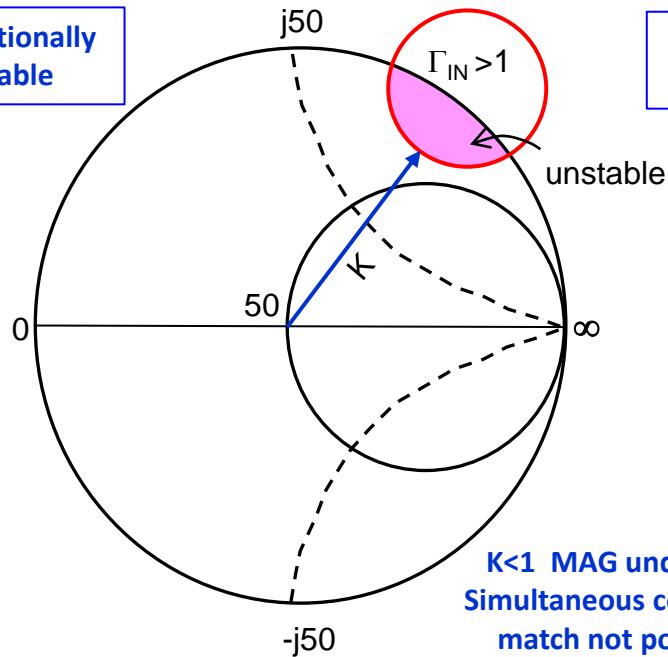


$\Gamma_{out} = 1$ circle

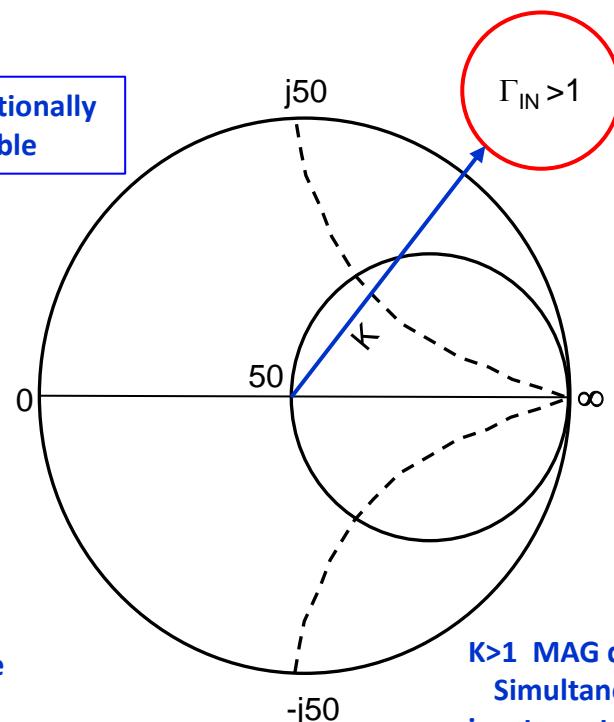


OUTPUT STABILITY CIRCLE & UNCONDITIONAL STABILITY

conditionally stable



unconditionally stable



**K<1 MAG undefined
Simultaneous conjugate
match not possible**

**K>1 MAG defined
Simultaneous
conjugate match possible**

$$K = \frac{1 + |S_{11}S_{22} - S_{12}S_{21}|^2 - |S_{11}|^2 - |S_{22}|^2}{2|S_{12}| |S_{21}|} = \text{Stability factor}$$

$$\Delta = |S_{11}S_{22} - S_{12}S_{21}|$$

For unconditional stability

$$K > 1 \text{ and } \Delta < 1$$

J.M.Rolett, IRE Trans CT, CT-9(1), pp 29-32, Mar 1962, W.Ku, Proc IEEE 54(11), pp 1617-1618, Nov 1966

GAIN EQUATIONS in S- Domain

Maximum Available Gain

$$\text{MAG} = \frac{|S_{21}|}{|S_{12}|} (K - \sqrt{K^2 - 1})$$

Use only for K>1

Maximum Stable Gain

$$\text{MSG} = \frac{|S_{21}|}{|S_{12}|}$$

Use only for K<1

Mason's Gain

$$U = \frac{|S_{21}/S_{12} - 1|^2}{2K |S_{21}/S_{12}| - 2\text{Re}(S_{21}/S_{12})}$$

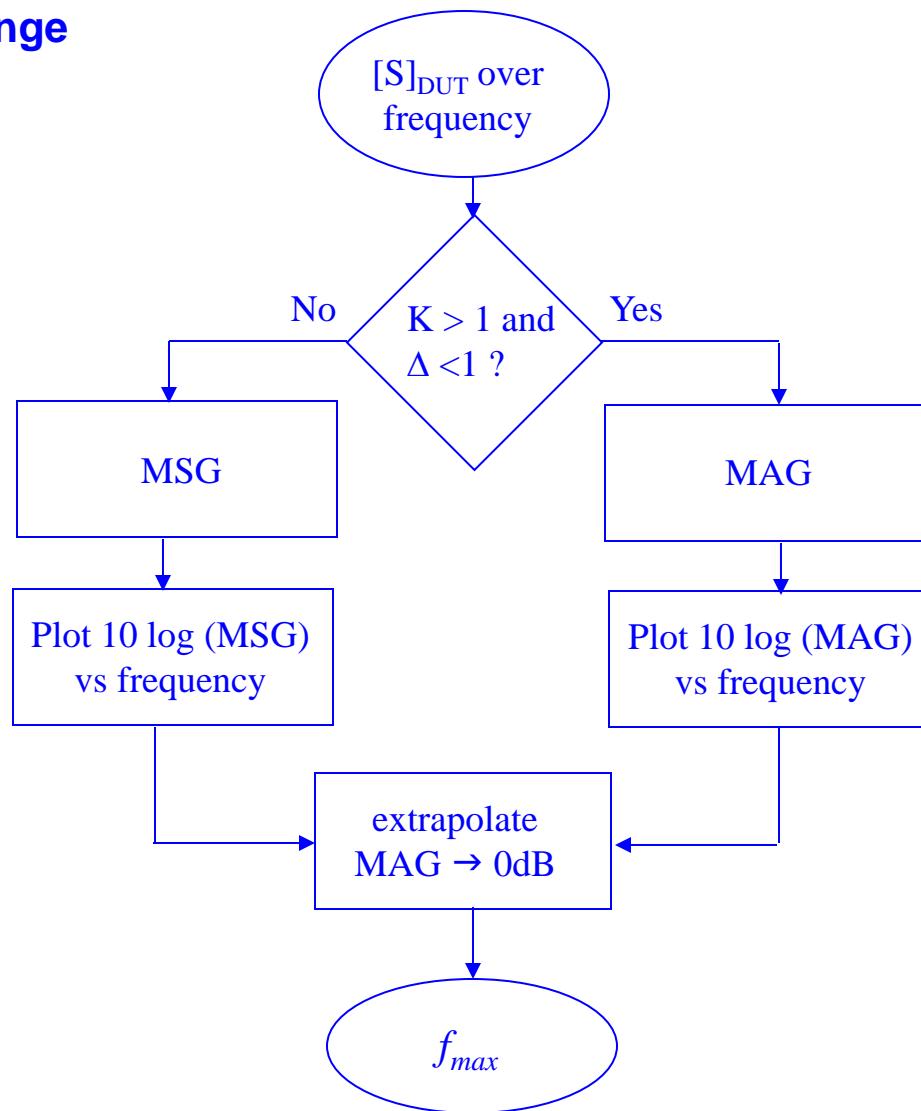
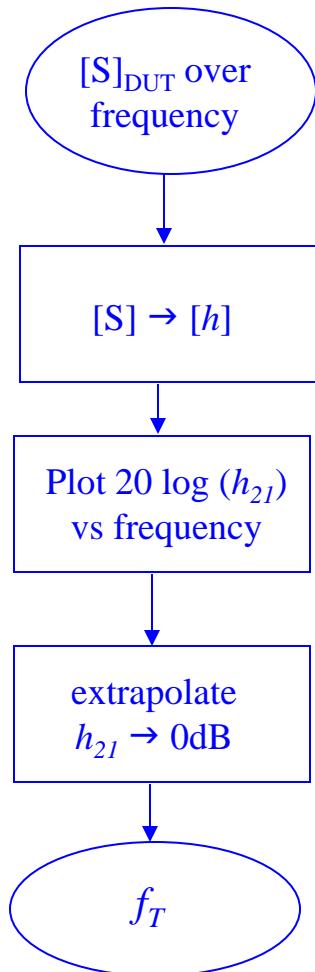
Use for all K
Does not depend on K

Current Gain

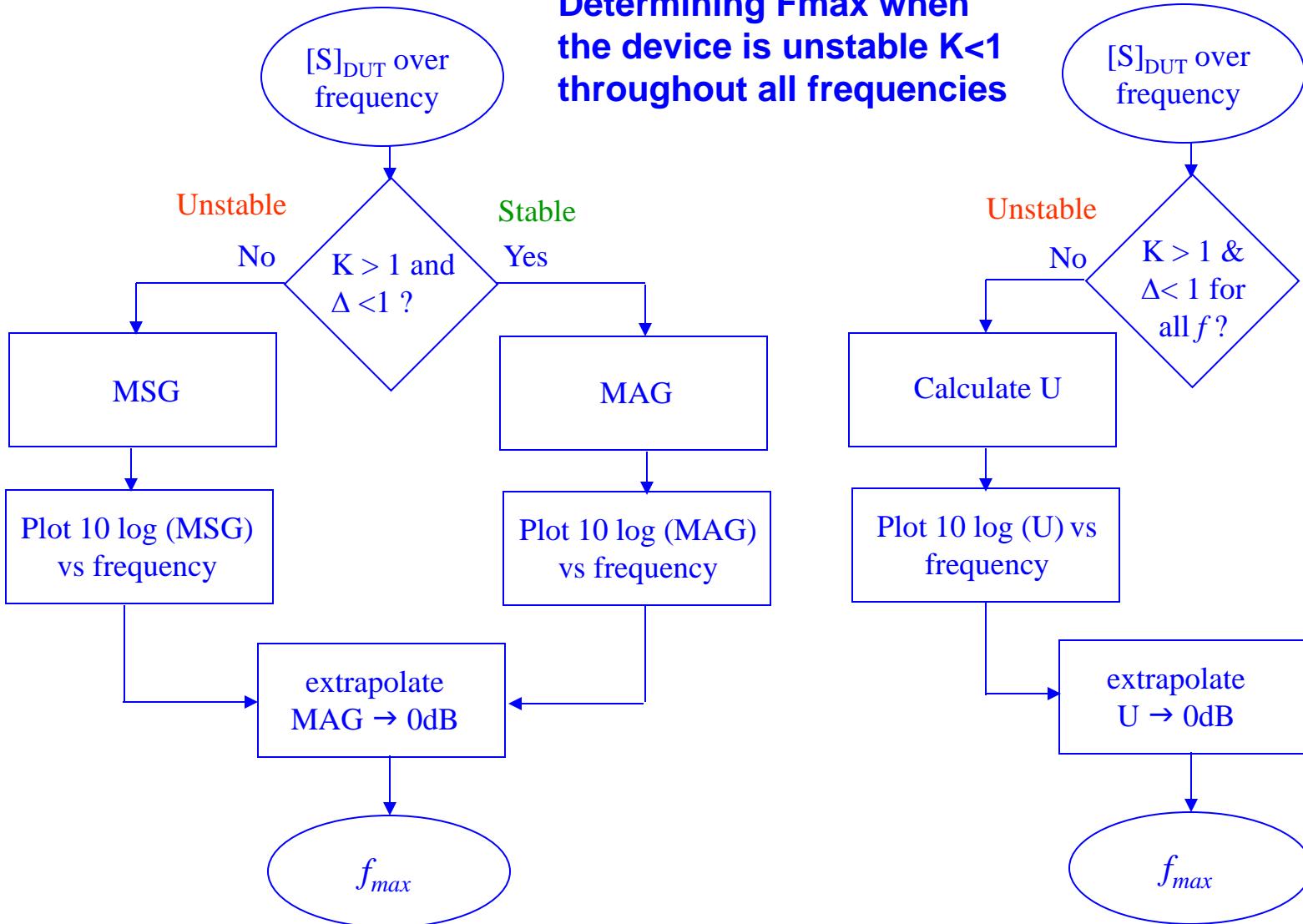
$$h_{21} = \frac{-2S_{21}}{(1 - S_{11})(1 + S_{22}) + S_{12}S_{21}}$$

Determining Ft and Fmax from Measured S-parameter Data

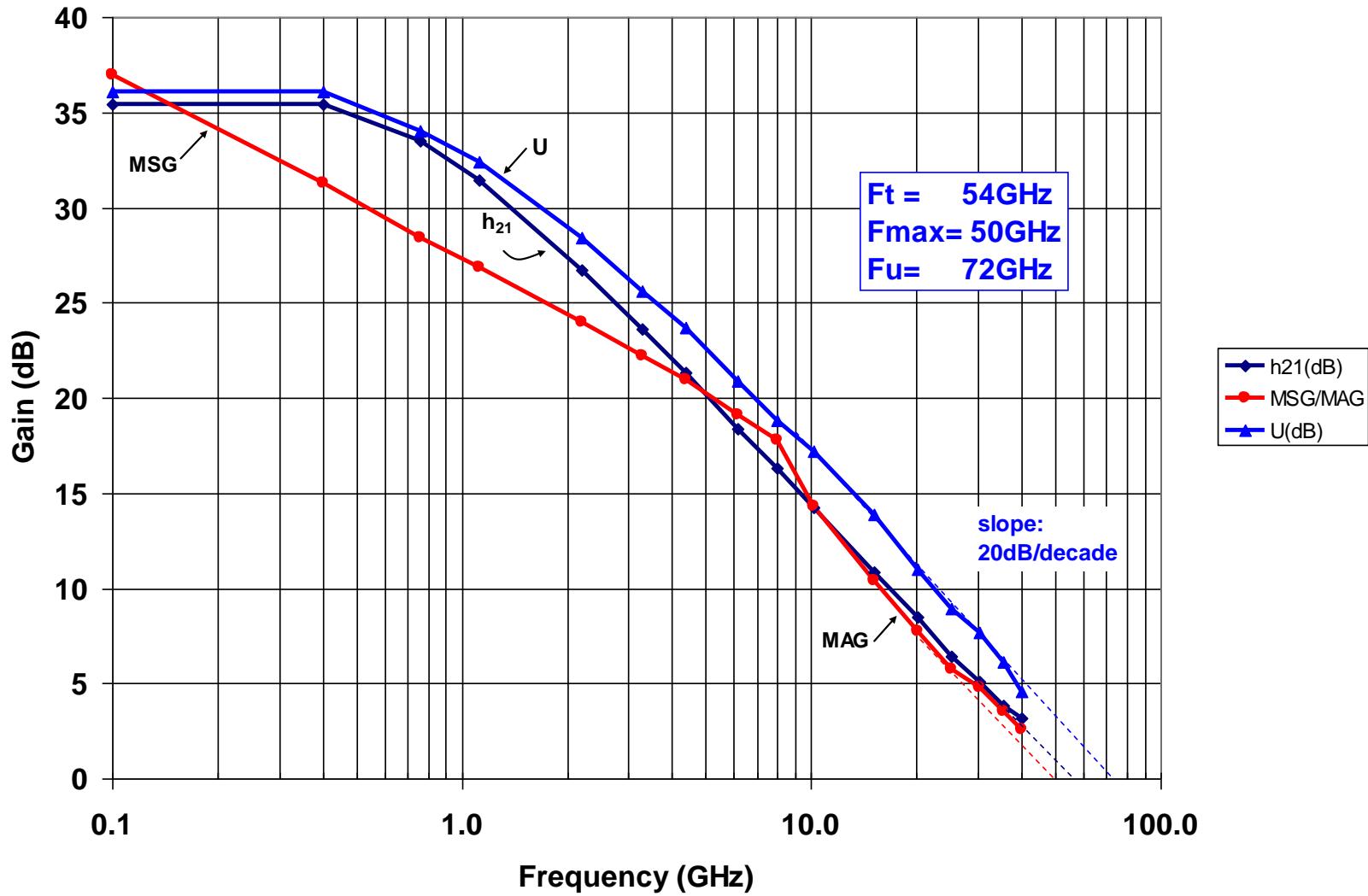
Determining Fmax when the device is stable $K > 1$ over some frequency range



Determining Fmax when the device is unstable K<1 throughout all frequencies

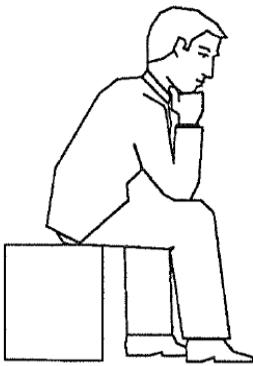


HF performance of $3\mu\text{x}10\mu$ HBT $I_c=10\text{mA}$ $V_{ce}=2\text{V}$



Mason's Gain Explained

If Fmax is a Figure of Merit, is it Unique?



MAG will be different in different configurations (CE,CB,CC). Then, when I extrapolate MAG will I get different Fmax for different configurations ?

If the device is unstable throughout the band of frequencies, should I extrapolate MSG to find Fmax ?

The device becomes unstable because of S12.

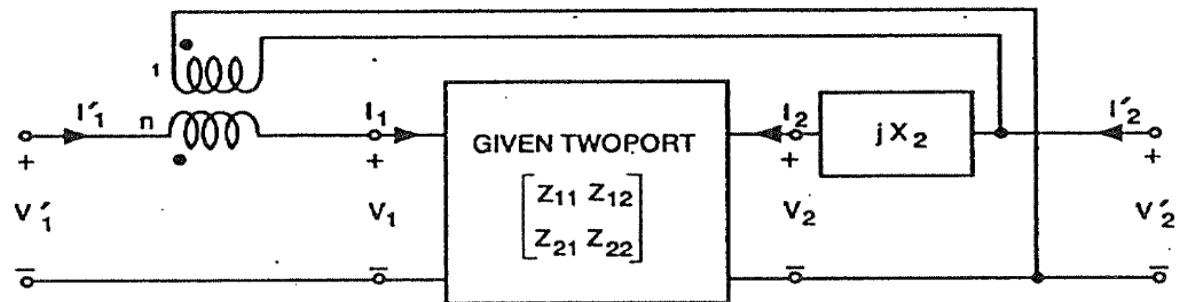
Is there a way to make $S_{12}=0$ so that I can always compute stable gain and find Fmax ?

Is there a way gain can be defined so that it is independent of the configuration ?

Can the new definition of gain be consistent with the way MAG is extrapolated ?

How can I find out whether a device is Active or Passive?

Method of unilateralizing a Two Port Network



$$\begin{bmatrix} Z_{11} & 0 \\ Z_{21} & Z_{22} \end{bmatrix}$$

Add a reactance jX_2 at the output such that the voltage V_2 is exactly out of phase with V_1 when $I_1=0$. Choose a turns ratio such that the voltage introduced cancels out the reverse voltage transfer through the device.

POWER GAIN CALCULATIONS IN DIFFERENT CONFIGURATIONS

Parameter	CE	CC	CB
S ₁₁	$0.33\angle -111^\circ$	$0.91\angle -29.03^\circ$	$0.71\angle 159.32^\circ$
S ₁₂	$0.09\angle 52^\circ$	$0.27\angle 59.44^\circ$	$0.04\angle 84.04^\circ$
S ₂₁	$3.79\angle 96^\circ$	$1.58\angle -22.71^\circ$	$1.65\angle -25.32^\circ$
S ₂₂	$0.51\angle -29^\circ$	$0.67\angle 143.02^\circ$	$0.99\angle -15.64^\circ$
K	1.09	0.19	0.03
h _{fe} dB	14.38	14.31	-0.11
MAG dB	14.47	***	***
MSG dB	16.24	7.59	16.00
U dB	17.45	17.45	17.45

MASON'S INVARIANT or UNILATERAL GAIN U

$$U = \frac{|y_{12} - y_{21}|^2}{4[\operatorname{Re}(y_{11})\operatorname{Re}(y_{22}) - \operatorname{Re}(y_{12})\operatorname{Re}(y_{21})]}$$

$$U = \frac{|z_{12} - z_{21}|^2}{4[\operatorname{Re}(z_{11})\operatorname{Re}(z_{22}) - \operatorname{Re}(z_{12})\operatorname{Re}(z_{21})]}$$

$$U = \frac{|S_{12} - S_{21}|^2}{\det[1 - SS^*]}$$

If $U > 1$, DEVICE IS ACTIVE

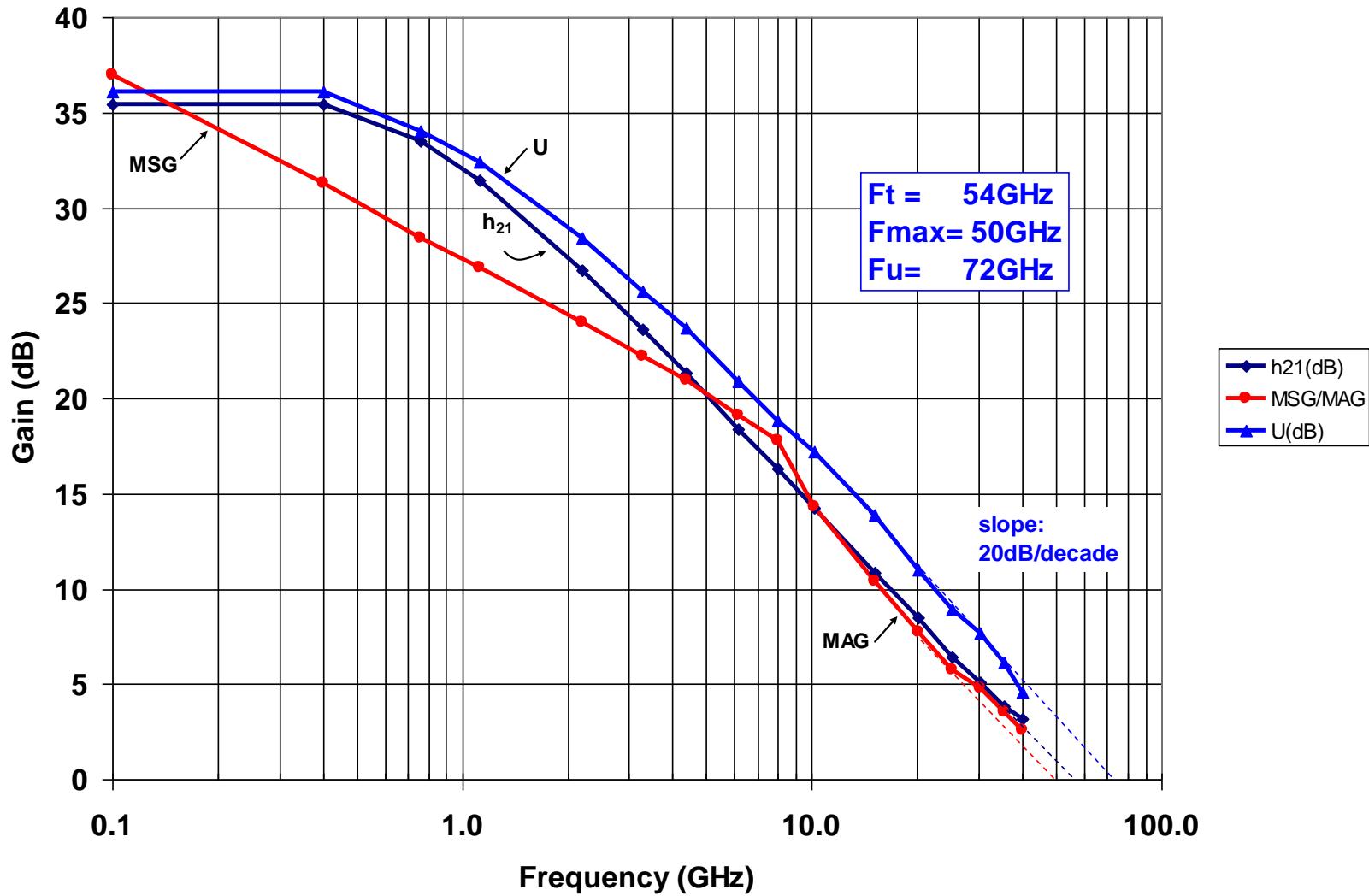
If $U < 1$, DEVICE IS PASSIVE

S.J.Mason, IRE Tran CT, CT-1 (2), pp 20-25, June 1954

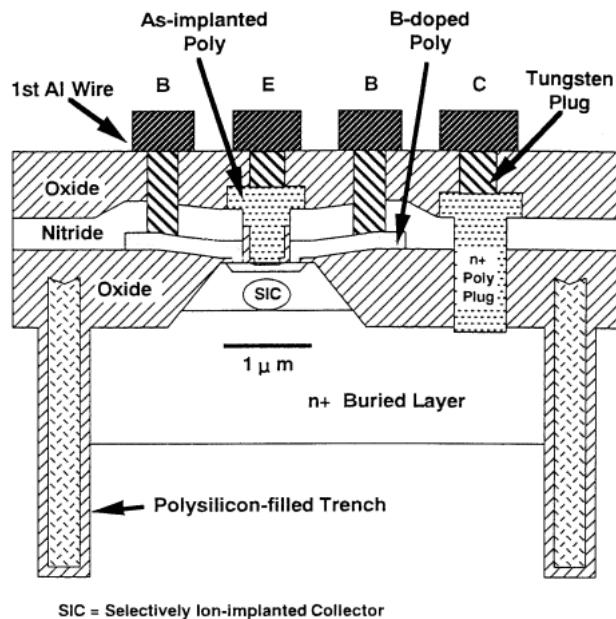
M.S.Gupta, T-MTT, 40(5), pp 864-879, 1992

Transistor Specmanship!

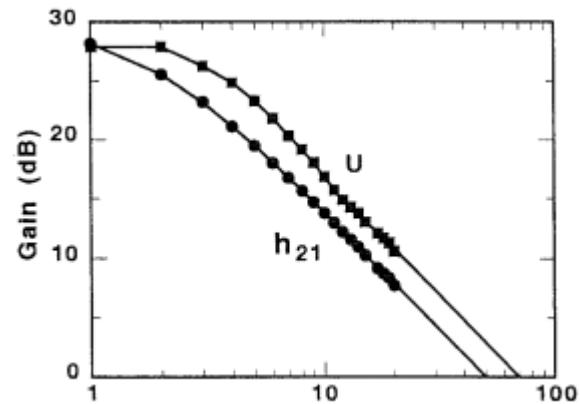
HF performance of $3\mu\text{m} \times 10\mu\text{m}$ HBT $I_c=10\text{mA}$ $V_{ce}=2\text{V}$



70GHz Fmax Silicon Bipolar Transistor

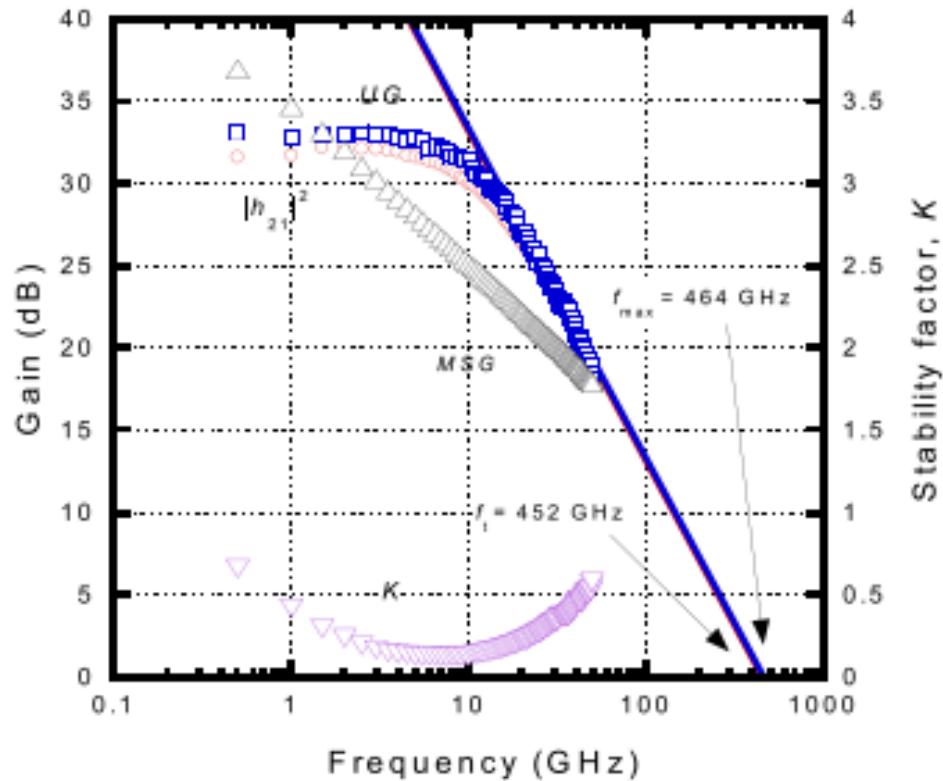
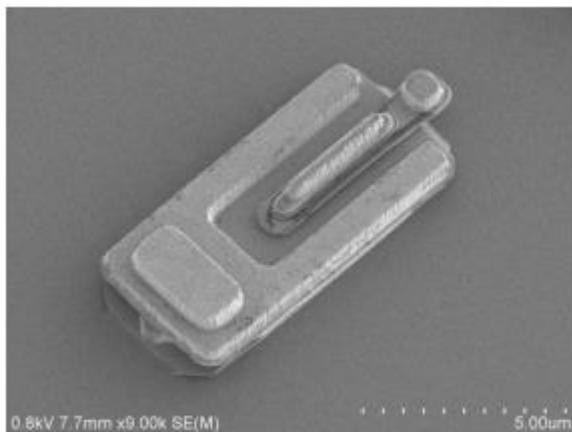


Mamoru Ugajin, Jun-ichi Kodate, Yoshiji Kobayashi, Shinsuke Konaka, and Tetsushi Sakai NTT LSI Laboratories 3-1, Morinosato Wakamiya, Atsugi-Shi, Kanagawa, 243-01 Japan
IEDM95



Emitter Area (μm^2)	1.5 × 0.3	0.6 × 0.3
β_{MAX}	60	60
R_B (Ω)	156	230
R_E (Ω)	60	120
R_C (Ω)	167	336
BV_{CEO} (V)	3	3
BV_{CBO} (V)	10	10
BV_{EBO} (V)	4.5	4.5
Early Voltage (V)	9	9
C_{JC} (fF)	2.7	1.8
C_{JE} (fF)	2.8	1.3
peak f_T (GHz)		
@ $V_{CE} = 1.0$ V	44	42
@ $V_{CE} = 2.5$ V	50	47
peak f_{MAX} (GHz)		
@ $V_{CE} = 1.0$ V	55	53
@ $V_{CE} = 2.5$ V	70	65

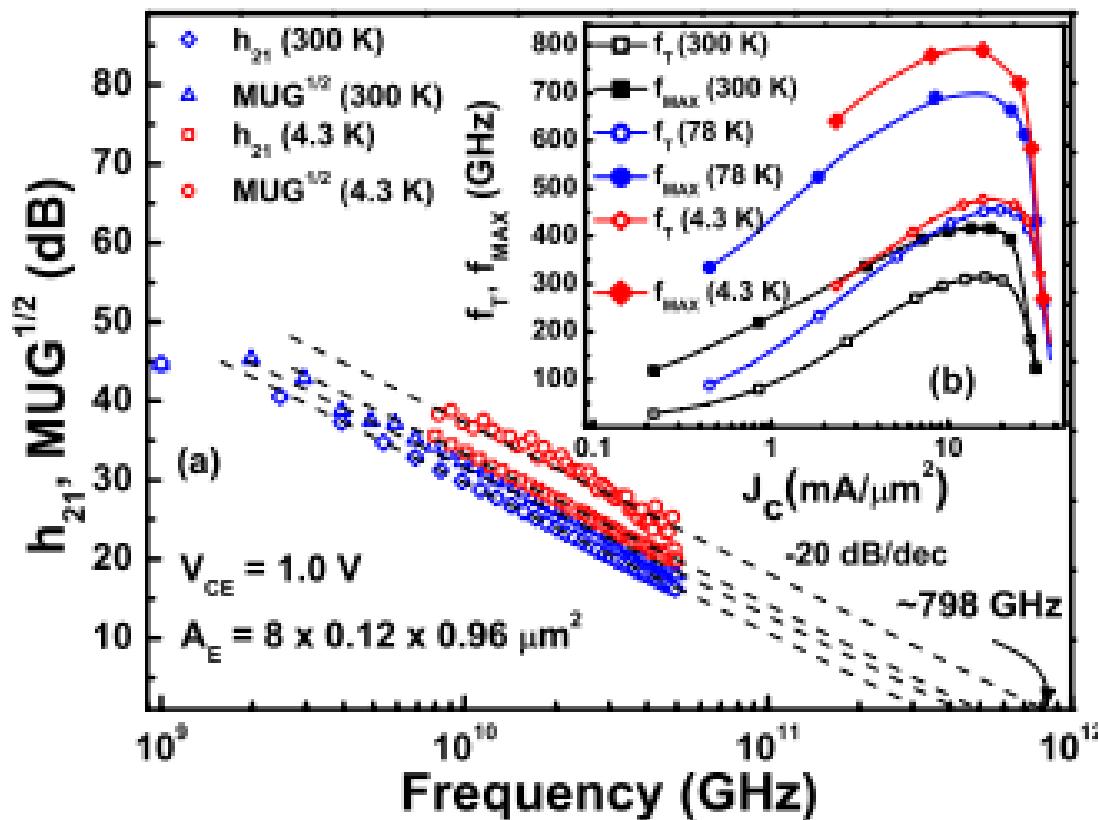
450GHz f_t and f_{max} InP/InGaAs HBT



N. Kashio et al., TED 61(10), Oct 2014 p 3423

High Frequency Performance of 0.12um SiGe HBT

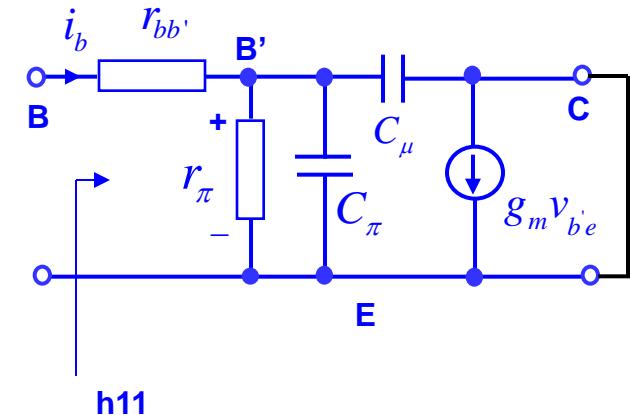
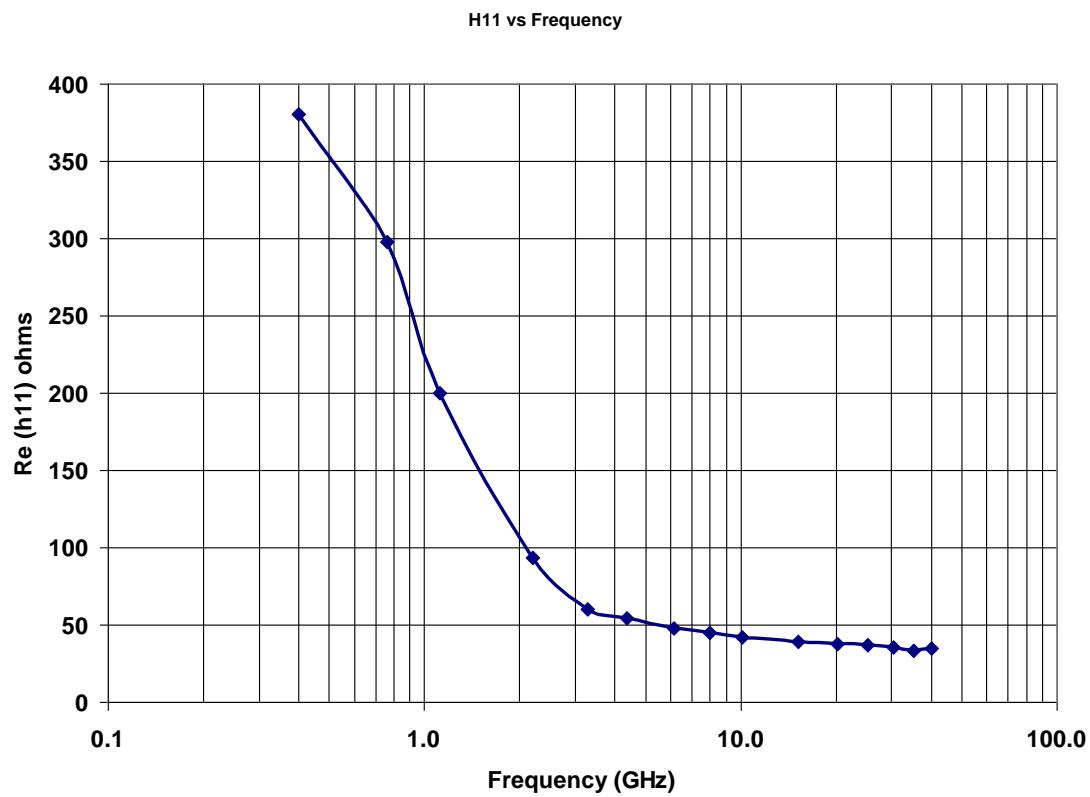
IEEE ELECTRON DEVICE LETTERS, VOL. 35, NO. 2, FEBRUARY 2014



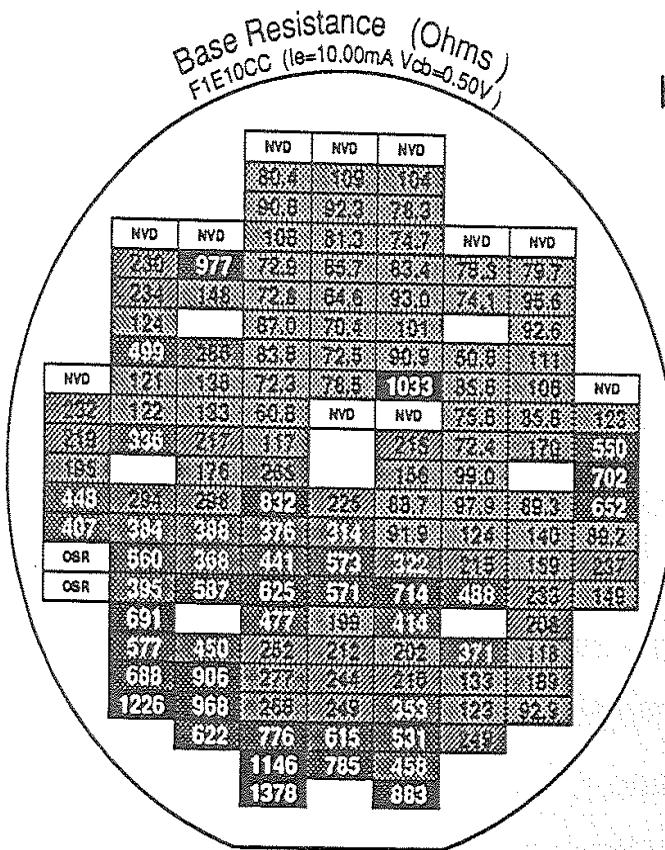
Other uses of S-parameter Measurements:

Parameter Extraction for SPICE

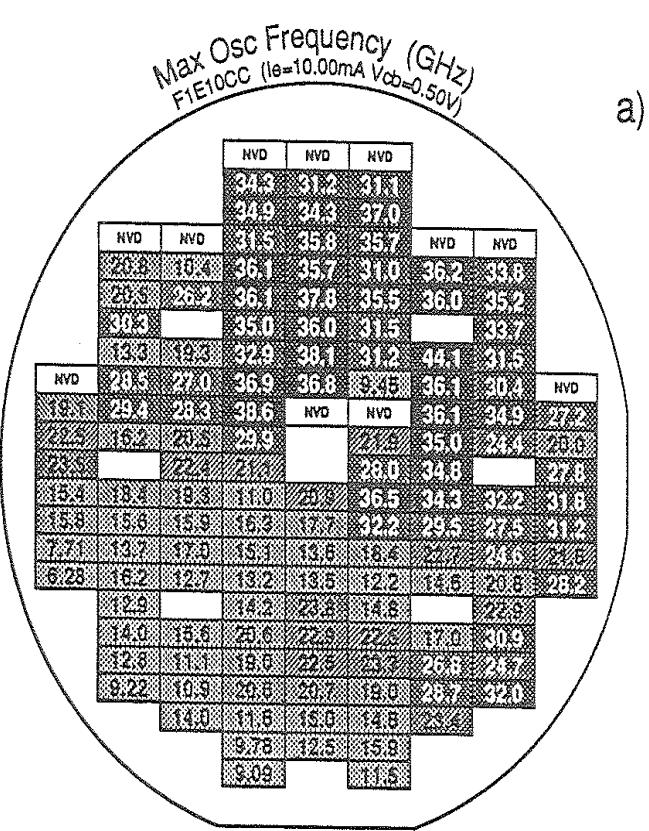
Base resistance extraction from h_{11}



Wafer Map of Base Resistance and Fmax



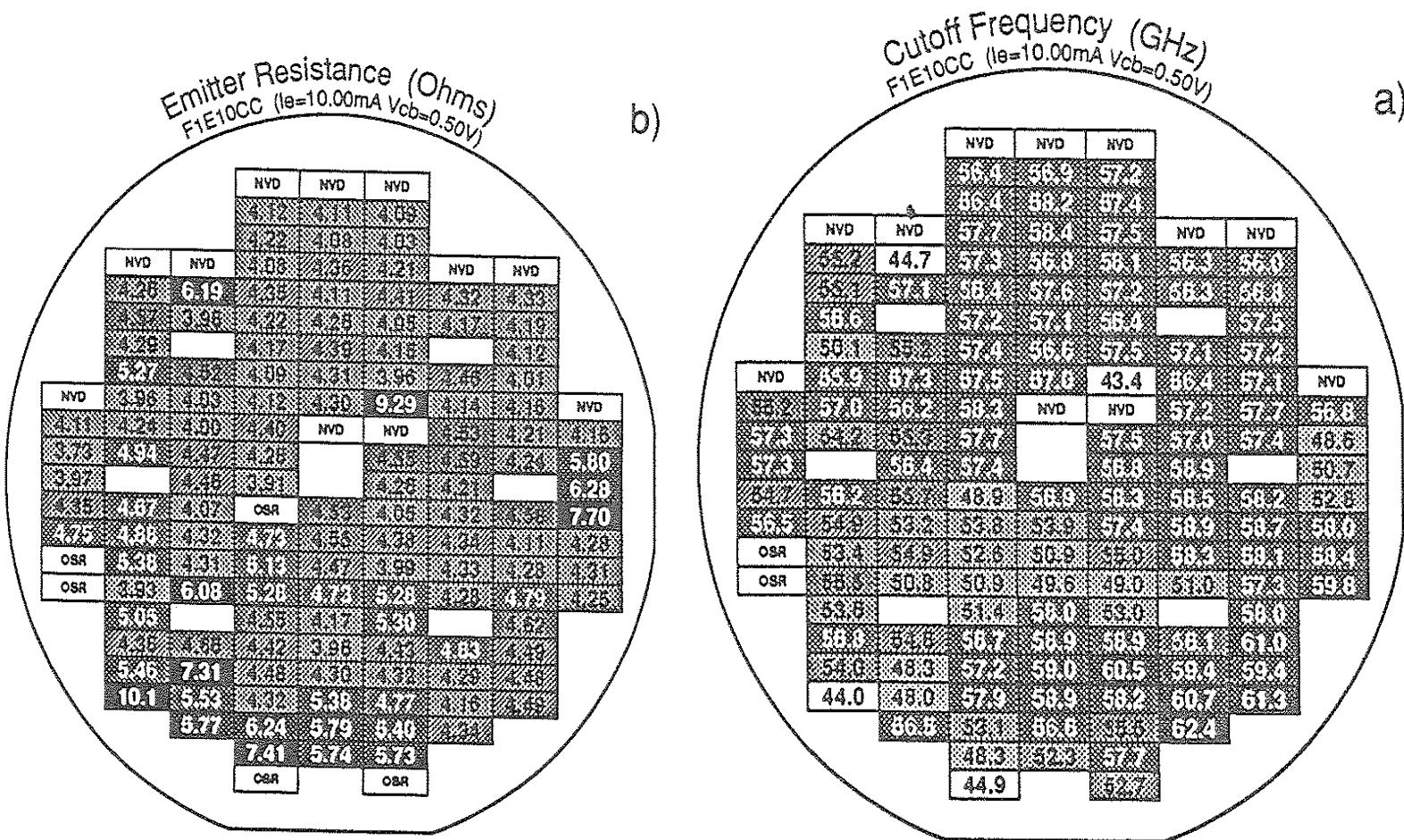
b)



a)

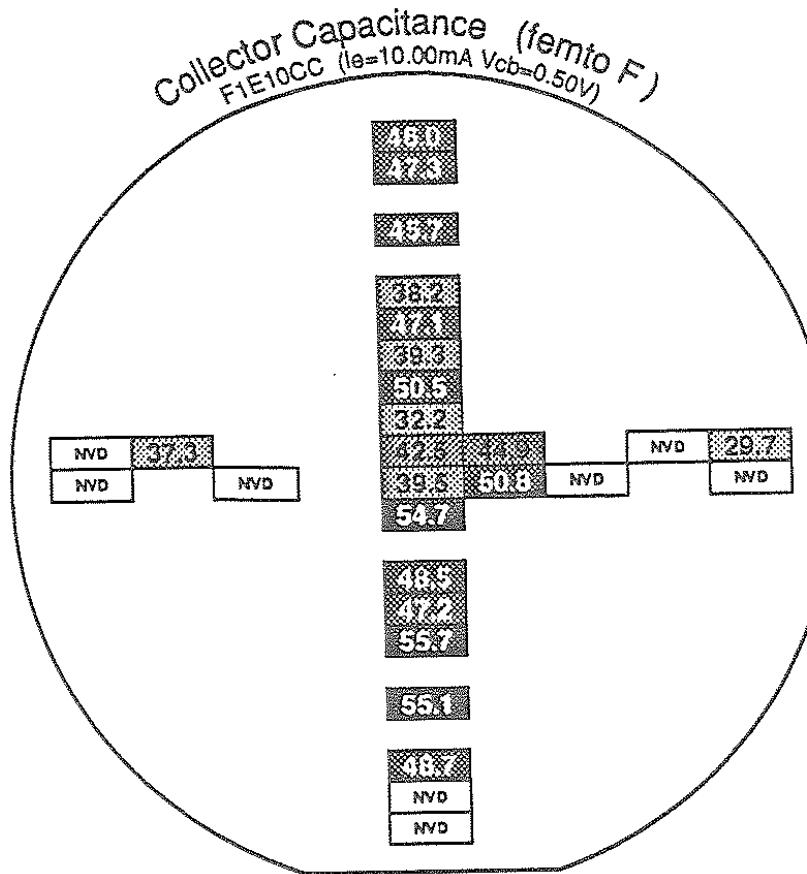
S.J. Prasad, BCTM 1992, pp 204-207

Wafer Map of Emitter resistance and Ft



S.J. Prasad, BCTM 1992, pp 204-207

Wafer Map of Collector Capacitance



S.J. Prasad, GaAs IC Symposium 1992, pp 271- 274

ENGINEERING

It is a great profession.

*There is the fascination of watching a figment of imagination
emerge through the aid of science to a plan on paper.*

Then it moves to realization in stone or metal or energy.

Then it brings jobs and homes to men.

Then it elevates the standards of living and adds comforts to life.

That is the engineer's high privilege.

ENGINEERING - II

-- Herbert Hoover